TMD4903

Color and Proximity Sensor Module with mobeam™ Barcode Emulation and IR Remote Control

General Description

The TMD4903 features ambient light and color (RGB) sensing, proximity detection and IRBeam optical pattern generator capable of mobeam™ barcode emulation and IR remote control. In addition, the device integrates an IR LED and advanced LED driver, all within a low-profile and small footprint, 2.0mm x 5.0mm x 1.0mm package.

The Proximity sensing function synchronizes IR emission and detection to sense proximity events. The architecture of the engine features self-maximizing dynamic range, ambient light subtraction, advanced crosstalk cancelation, 14-bit data output, 32-dataset FIFO, and interrupt-driven I^2C communication. Sensitivity, power consumption, and noise can be optimized with adjustable IR LED timing and power. The proximity engine recognizes detect/release events and produces a configurable interrupt whenever proximity result crosses upper or lower threshold settings.

The Ambient Light and Color Sensing function provides Red, Green, and Blue (RGB) ambient light sensing with a Clear reference (C). The color diode array has a UV/IR blocking filter and parallel ADCs to produce simultaneous 16-bit results. This architecture accurately measures ambient light and enables the calculation of illuminance, chromaticity, and color temperature to manage display appearance.

The IRBeam pattern generator supports mobeam™ barcode emulation and IR remote control. The engine features RAM for pattern storage and specialized control logic that is tailored to repetitively broadcast a barcode pattern using the integrated LED or an external LED with a low side driver. The IRBeam engine features adjustable timing, looping, and IR intensity to maximize successful transmission. IRBeam is designed to support all requirements for 1-D barcode transmission over IR to point-of-sale (POS) terminals as well as IR remote control.

Ordering Information and Content Guide appear at end of datasheet.

Key Benefits & Features

The benefits and features of TMD4903, Color and Proximity Sensor Module with mobeam™ Barcode Emulation and IR Remote Control are listed below:

Figure 1:
Added Value of Using TMD4903

Benefit	Feature
Proximity detection	• Selectable direction sensitivity • Ambient light rejection • Advanced crosstalk compensation • AFE saturation flag • Programmable LED driver • Interrupt-Driven I^2C communication
Ambient light and color sensing	• Variable sensitivity • Designed to operate behind inked glass • UV/IR blocking filter • Programmable gain and integration time • 6.7M:1 dynamic range by gain adjustment only • Interrupt-driven I^2C communication
IRBeam pattern generator	• mobeam™ support • Universal remote control support • Interrupt-driven I^2C communication
Integrated LED and driver	• Calibrated emission and response • Invisible 950nm emission
Low supply voltage	• 1.8V operation

Applications

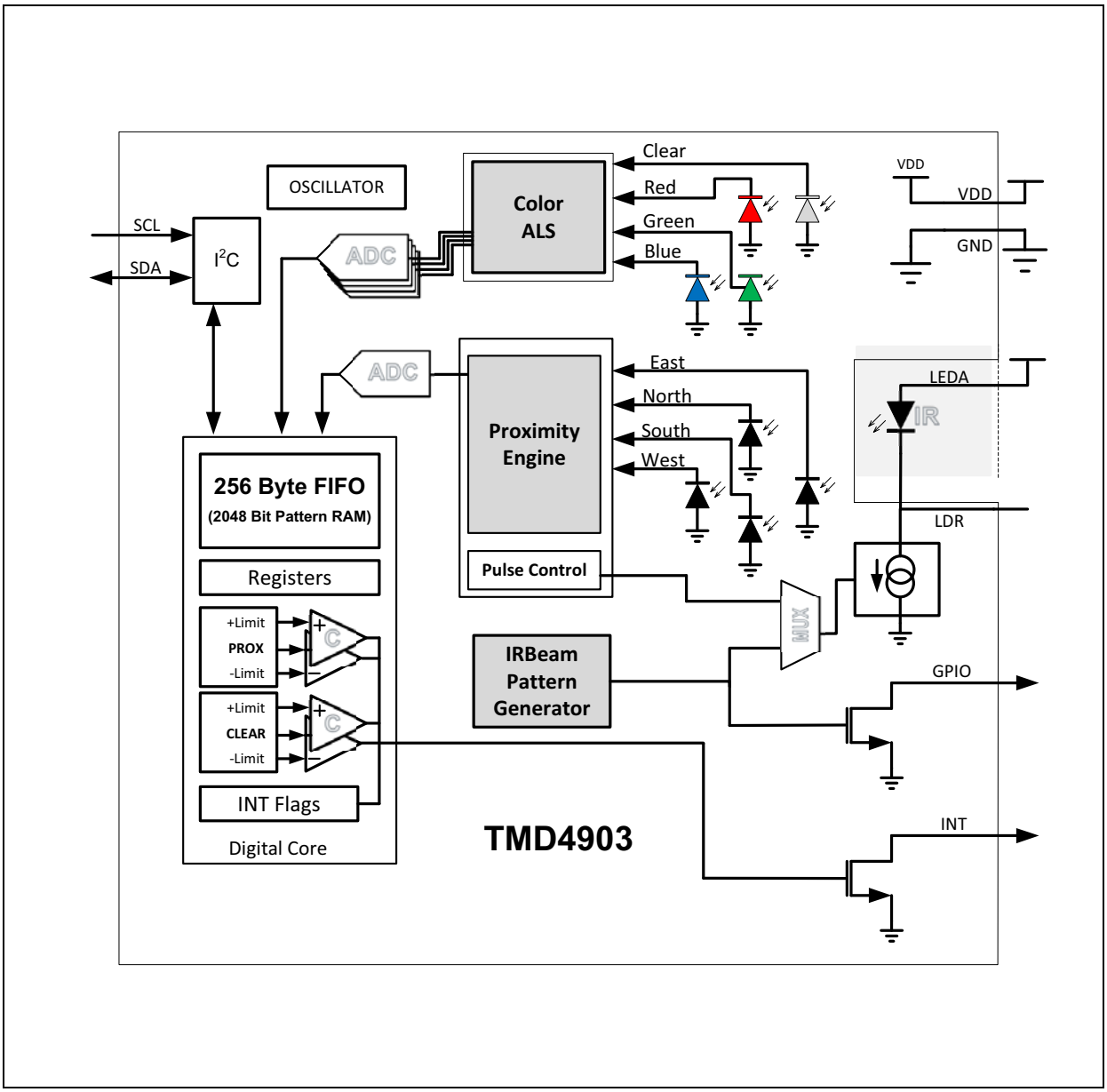
The TMD4903 applications include:

- Color sensing
- Ambient light sensing
- Cell phone touch screen disable
- Mechanical switch replacement
- 1D barcode emulation
- Universal remote control

Block Diagram

The functional blocks of this device for reference are shown below:

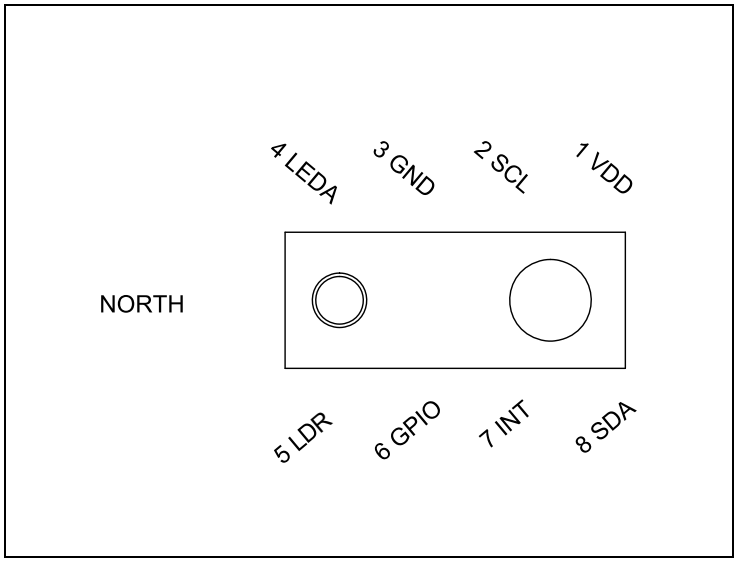
Figure 2:
TMD4903 Block Diagram



Pin Assignment

The device pin assignments are described below.

Figure 3:
Pin Diagram



Pin Description

Figure 4:
Pin Description

Pin Number	Pin Name	Description
1	V_{DD}	Supply voltage (1.8V)
2	SCL	I^2C serial clock terminal
3	GND	Ground. All voltages are referenced to GND
4	LEDA	LED anode
5	LDR	LED driver (sinks current) and LED cathode (for direct access to LED)
6	GPIO	Open drain IRBeam output or alternate interrupt
7	INT	Interrupt. Open drain output and logic level output for external IR LED circuit
8	SDA	I^2C serial data I/O terminal

Absolute Maximum Ratings

Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Figure 5:
Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Units	Comments
V_{DD}	Supply voltage	-0.3	2.2	V	
V_{LEDA}	LED anode supply	-0.3	3.6	V	
V_{IO}	Digital I/O terminal voltage	-0.3	3.6	V	
V_{LDR}	Terminal voltage	-0.3	3.6	V	see note (2)
I_{IO}	Output terminal current	-1	20	mA	
T_{stg}	Storage temperature range	-40	85	°C	
ESD_{HBM}	ESD tolerance, human body model	±2000		V	

Note(s) and/or Footnote(s):

1. All voltages with respect to GND
2. Measured with LDR = OFF or LDR = ON and LDRIVE = 310mA.

Electrical Characteristics

The parameters with min and max values are guaranteed with production tests or SQC (Statistical Quality Control) methods.

Figure 6:
Recommended Operating Conditions

Symbol	Parameter	Min	Typ	Max	Units
V_{DD}	Supply voltage	1.7	1.8	2.0	V
T_A	Operating free-air temperature (1)	-30		85	°C

Note(s) and/or Footnote(s):

1. While the device is operational across the temperature range, functionality will vary with temperature. Specifications are stated at 25°C, unless otherwise noted.

Figure 7:
Operating Characteristics, VDD = 1.8 V, TA = 25°C (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
f_{OSC}	Oscillator Frequency			8.1		MHz
I_{DD}	Supply current (1)	Active ALS state (PON=AEN=1, PEN=IBEN=0) (2)	90	150	200	µA
		Idle state (PON=1, AEN=PEN=IBEN=0) (3)		30	60	
		Sleep State (4)		0.4	5	
V_{OL}	INT, SDA, GPIO output low voltage	6 mA sink current			0.6	V
I_{LEAK}	Leakage current, SDA, SCL, INT, GPIO, LDR pins		-5		5	µA
V_{IH}	SCL, SDA input high voltage		1.26			V
V_{IL}	SCL, SDA input low voltage				0.54	V

Note(s) and/or Footnote(s):

1. Values are shown at the VDD pin and do not include current through the IR LED.
2. This parameter indicates the supply current during periods of ALS integration. If Wait is enabled (WEN=1), the supply current is lower during the Wait period.
3. Idle state occurs when PON=1 and all functions are not enabled.
4. Sleep state occurs when PON = 0 and I^2C bus is idle. If Sleep state has been entered as the result of operational flow, SAI = 1, PON will remain high.

Figure 8:
ALS/Color Operating Characteristics, VDD = 1.8 V, TA = 25°C, AGAIN = 16x, ATIME = 0xF6 (unless otherwise noted)

Parameter	Conditions	Min	Typ	Max	Units
Integration time step size[1], [2]		2.68	2.78	2.90	ms
Dark ADC count value [2]	E_e = 0 µW/ cm^2 AGAIN: 64x ATIME: 100ms (0xDC)	0	1	3	counts
Gain scaling, relative to 16x gain setting	AGAIN: 1/4x	0.0135		0.0175	x
	AGAIN: 1x	0.058		0.067	
	AGAIN: 4x	0.237		0.263	
	AGAIN: 64x	3.75		4.37	
Clear channel irradiance responsivity	White LED, 2700K	8.94	10.28	11.62	counts/ (µW/ cm^2)
Lux accuracy [3]	White LED, 2700K	90	100	110	%
ADC Noise [4]	AGAIN: 16x		0.005		% Full Scale

Note(s) and/or Footnote(s):

1. Integration time is configured from 1 step (0xFF) to 256 steps (0x00) for a typical range of 2.78ms to 711.11ms. An ATIME setting of 0xFF results in a full-scale count value of 1024. Each additional integration step adds 1024 counts to full scale. To enable 16-bit ADC range, 64 or more integration steps (177.8ms or more) are required (ATIME <= 0xC0).
2. The typical 3-sigma distribution is between 0 and 1 count for an AGAIN setting of 16x.
3. Lux accuracy is function of red, green, blue and clear channels, and not 100% production tested.
4. ADC noise is calculated as the standard deviation of 1000 data samples.

Figure 9:
Color Ratio Characteristics, VDD = 1.8V, TA = 25°C

Parameter	Test Conditions	Ratio of Color to Clear Channel					
		Red Channel		Green Channel		Blue Channel	
		Min	Max	Min	Max	Min	Max
Color ADC count value ratio: Color/Clear	White LED, 2700 K	45%	65%	19%	39%	15%	40%
	λ_D = 465 nm (1)	0%	15%	10%	42%	70%	90%
	λ_D = 525 nm (2)	4%	25%	60%	85%	10%	45%
	λ_D = 615 nm (3)	80%	110%	0%	14%	5%	24%

Note(s) and/or Footnote(s):

1. The 465 nm input irradiance is supplied by an InGaN light-emitting diode with the following characteristics: dominant wavelength λ_D = 465 nm, spectral halfwidth $\Delta\lambda_{½}$ = 22 nm.
2. The 525 nm input irradiance is supplied by an InGaN light-emitting diode with the following characteristics: dominant wavelength λ_D = 525 nm, spectral halfwidth $\Delta\lambda_{½}$ = 35 nm.
3. The 615 nm input irradiance is supplied by an AlInGaP light-emitting diode with the following characteristics: dominant wavelength λ_D = 615 nm, spectral halfwidth $\Delta\lambda_{½}$ = 15 nm.

Figure 10:
Proximity Operating Characteristics, VDD = 1.8 V, TA = 25°C (unless otherwise noted)

Parameter	Conditions	Min	Typ	Max	Unit
ADC conversion time step size			20		µs
Offset (no target response) (1)	PGAIN = 2 (4x) PGLDRIVE = 7 (150mA) PGPULSE_LEN = 1 (8us) No target present After electrical calibration		16	36	counts
Part to part variation (2)	PGAIN = 2 (4x) PGLDRIVE = 1 (30mA) PGPULSE_LEN = 1 (8us) d=23mm round target 30mm target distance After electrical calibration	75	100	125	%
Response, absolute (3)	PGAIN = 2 (4x) PGLDRIVE = 7 (150mA) PGPULSE_LEN = 1 (8us) 100x100mm, 90% reflective Kodak gray card 100mm target distance After electrical calibration	790	990	1190	counts
Noise/Signal (4)	PGAIN = 2 (4x) PGLDRIVE = 2 (50mA) PGPULSE_LEN = 1 (8us) PGPULSE = 7 (8 pulses)			2	%

Note(s) and/or Footnote(s):

1. Offset varies with power supply characteristics and system noise.
2. Production tested result is the average of 5 readings expressed relative to a calibrated response.
3. Representative result by characterization. Device settings can vary from 1 to 64 pulse count, 4µs to 32µs pulse width, 10mA to 310mA current setting, and 1x to 8x electrical gain. Refer to Figure 22 for device performance with different settings.
4. Production tested result is the range of 20 readings divided by the average response.

Figure 11:
Proximity Test Circuit

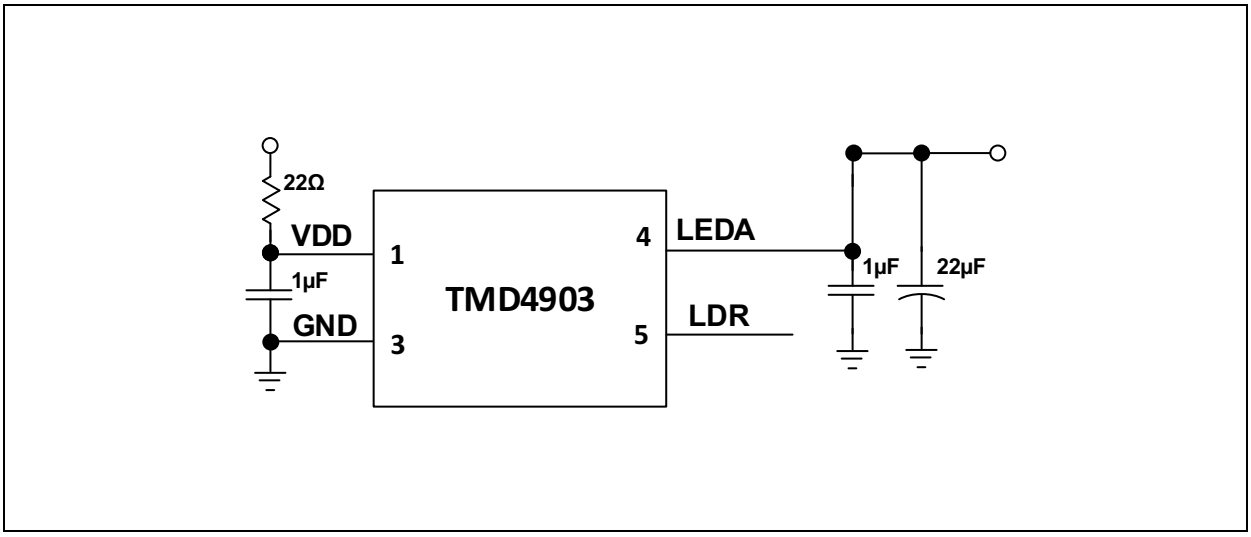


Figure 12:
Wait Characteristics, VDD = 1.8 V, TA = 25°C, WEN = 1 (unless otherwise noted)

Parameter	Conditions	Min	Typ	Max	Units
Wait step size		2.68	2.78	2.90	ms
Long wait step size			33.3		ms

Figure 13:
IRBeam Operating Characteristics, VDD = 1.8 V, TA = 25°C (unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$t_{(PBT\ min)}$	Minimum bit time	IBEN = 1		0.25		µs

Timing Characteristics

Figure 14:
AC Electrical Characteristics, VDD = 1.8 V, TA = 25°C (unless otherwise noted)

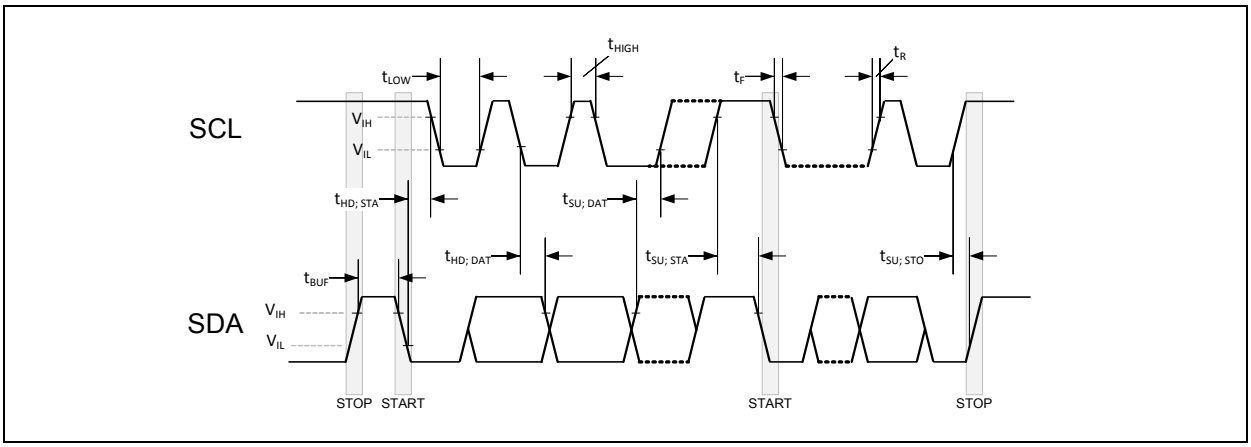
Parameter	Description	Min	Typ	Max	Unit
f_{SCL} (1)	Clock frequency (I^2C only)	0		400	kHz
t_{BUF} (1)	Bus free time between start and stop condition	1.3			µs
$t_{HS;STA}$ (1)	Hold time after (repeated) start condition. After this period, the first clock is generated.	0.6			µs
$t_{SU;STA}$ (1)	Repeated start condition setup time	0.6			µs
$t_{SU;STO}$ (1)	Stop condition setup time	0.6			µs
$t_{HD;DAT}$ (1)	Data hold time	0			ns
$t_{SU;DAT}$ (1)	Data setup time	100			ns
t_{LOW} (1)	SCL clock low period	1.3			µs
t_{HIGH} (1)	SCL clock high period	0.6			µs
t_F (1)	Clock/data fall time			300	ns
t_R (1)	Clock/data rise time			300	ns
C_i (1)	Input pin capacitance			10	pF

Note(s) and/or Footnote(s):

1. Specified by design and characterization; not production tested.

Timing Diagram

Figure 15:
Timing Parameter Measurement Drawing



Typical Operating Characteristics

Figure 16:
Spectral Responsivity

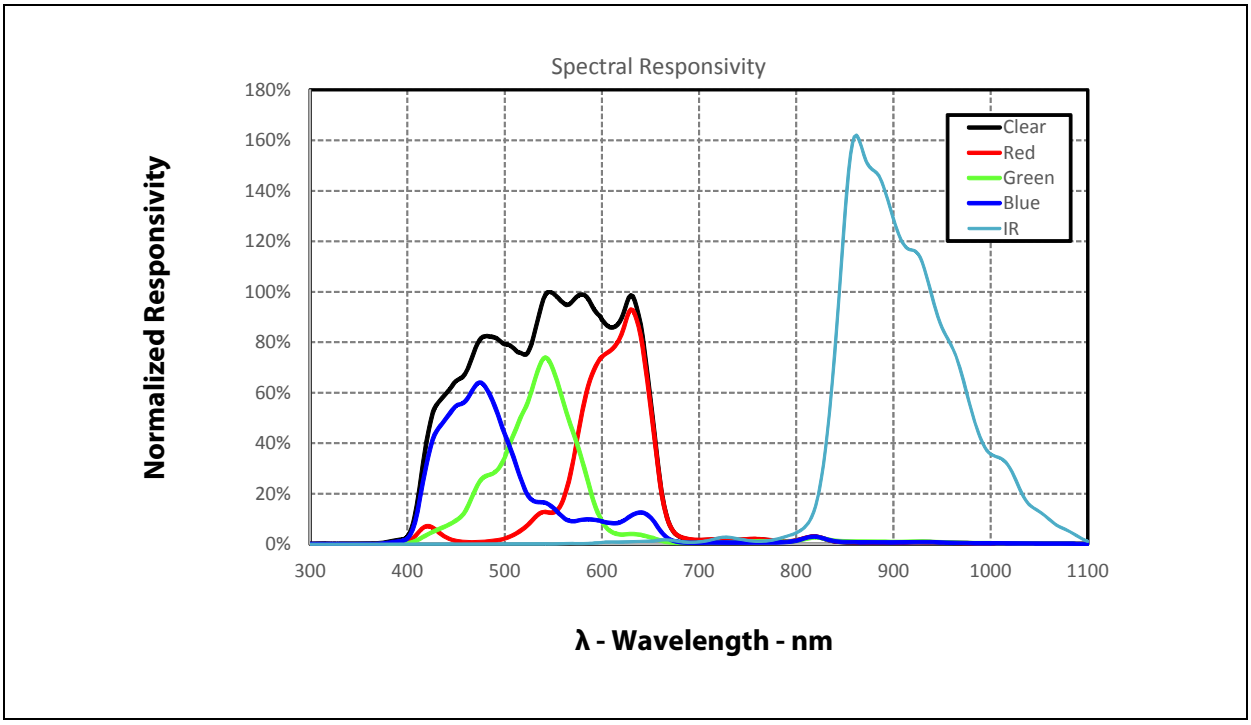


Figure 17:
CRGB Responsivity vs. Angular Displacement

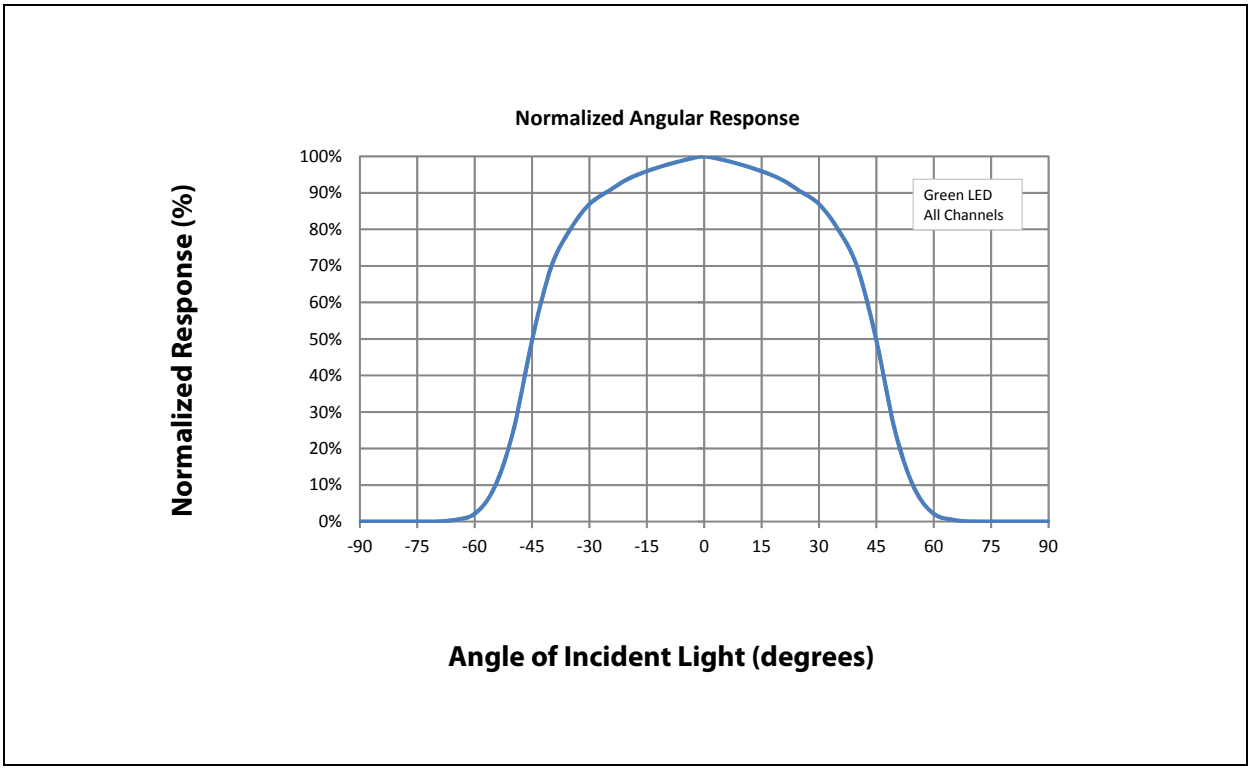


Figure 18:
Typical LDR Current vs. Voltage

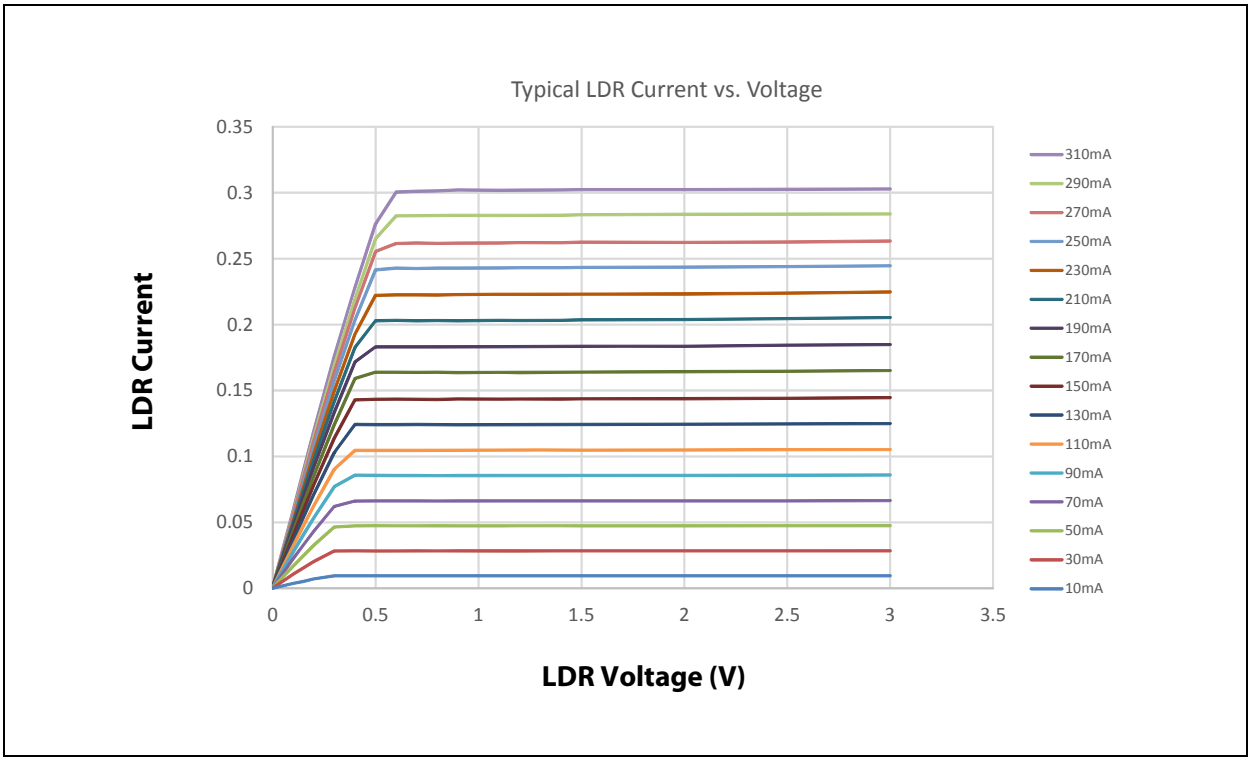


Figure 19:
Responsivity Temperature Coefficient

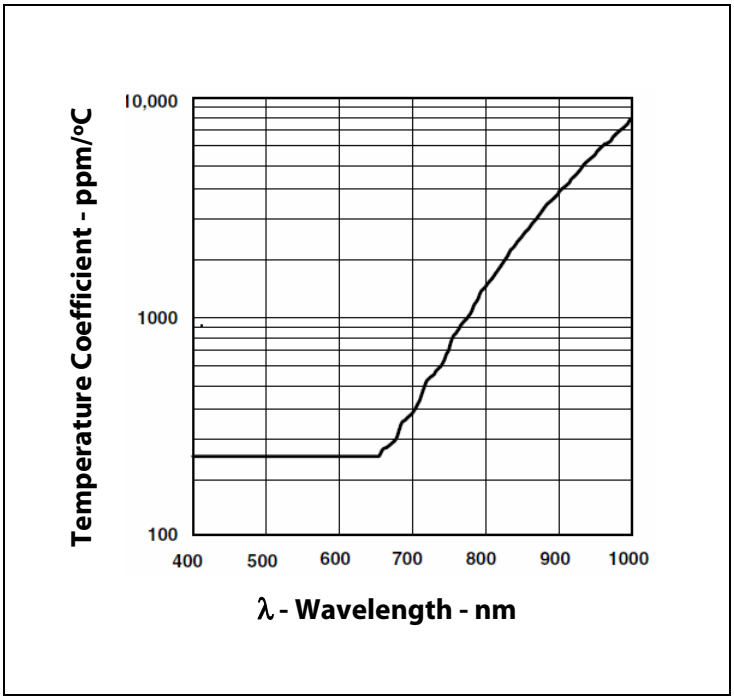


Figure 20:
Illuminance (Lux) vs. Counts (Clear Channel)

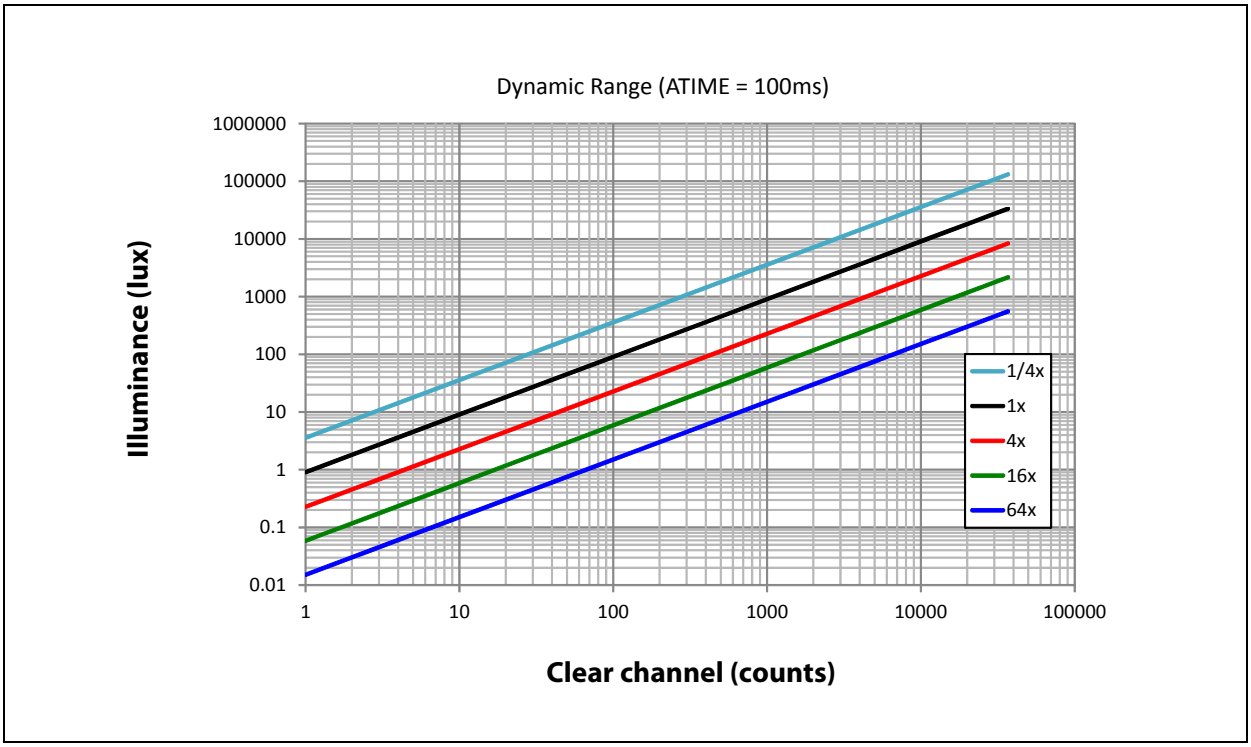
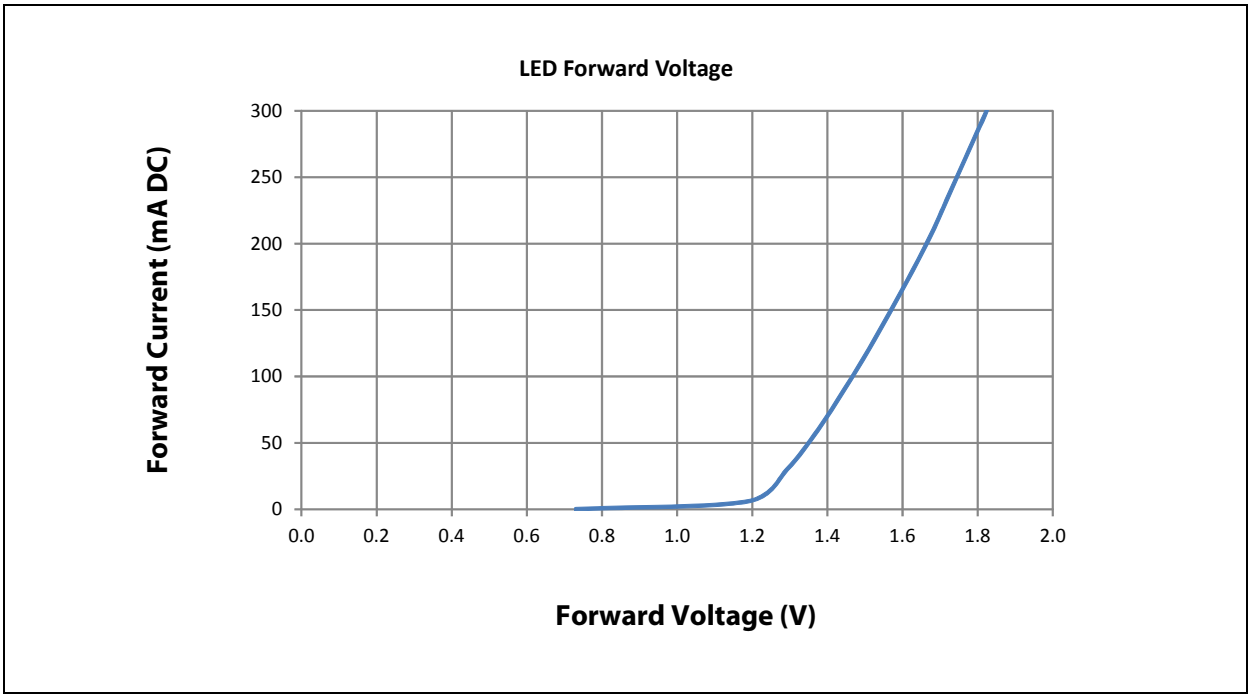


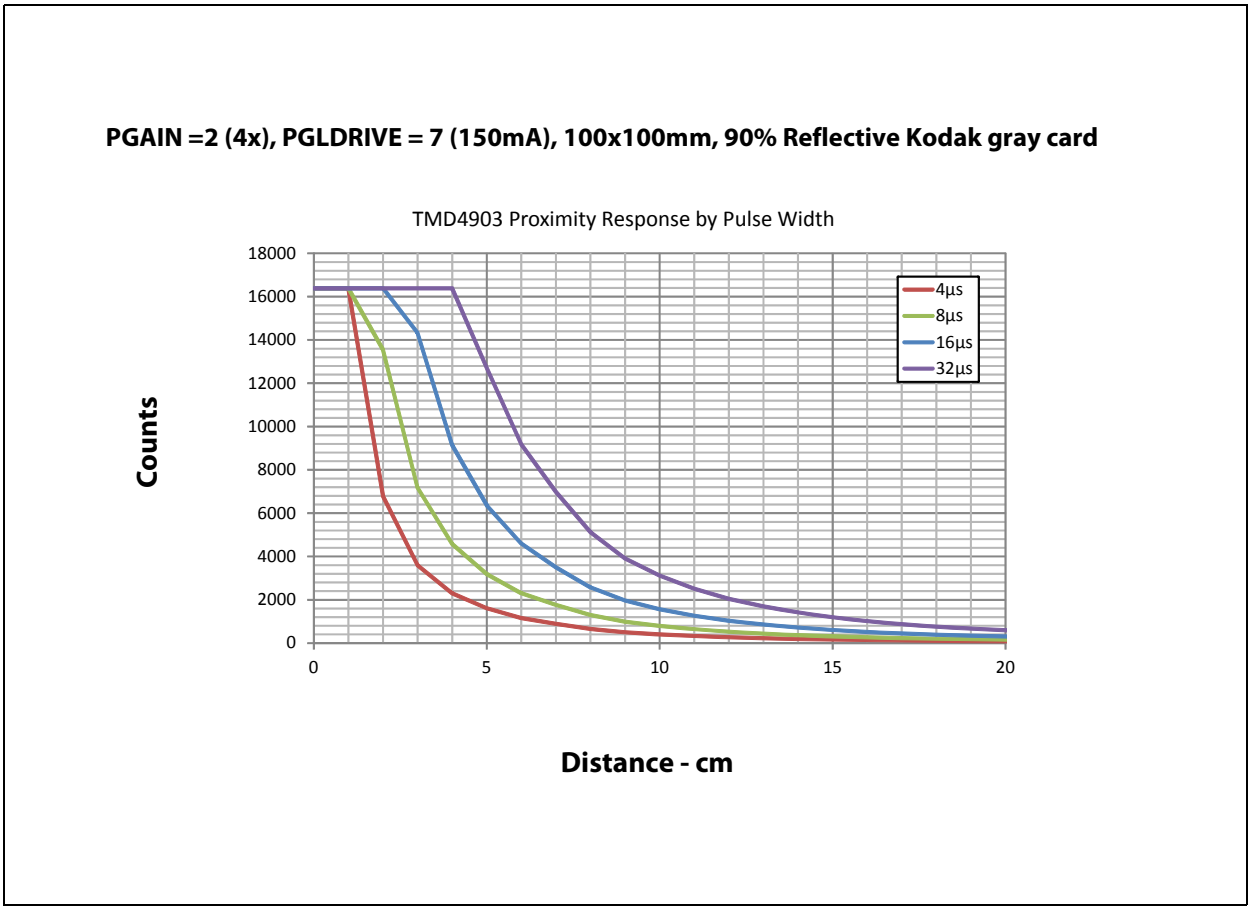
Figure 21:
950nm LED Forward Voltage vs. Current



Note(s) and/or Footnote(s):

1. The voltage on the LDR pin (VLEDA – VLED FORWARD) must be sufficiently large to guarantee proper operation of the regulated current sink.

Figure 22:
Proximity Response vs. Target Distance



I²C Protocol

The device uses I²C serial communication protocol for communication. The device supports 7-bit chip addressing and both standard and full-speed clock frequency modes. Read and Write transactions comply with the standard set by Philips (now NXP).

Internal to the device, an 8-bit buffer stores the register address location of the desired byte to read or write. This buffer auto-increments upon each byte transfer and is retained between transaction events (I.e. valid even after the master issues a STOP command and the I²C bus is released). During consecutive Read transactions, the future/repeated I²C Read transaction may omit the memory address byte normally following the chip address byte; the buffer retains the last register address +1.

All 16-bit fields have a latching scheme for reading and writing. In general it is recommended to use I²C bursts whenever possible, especially in this case when accessing two bytes of one logical entity. When reading these fields, the low byte must be read first, and it triggers a 16-bit latch that stores the 16-bit field. The high byte must be read immediately afterwards. When writing to these fields, the low byte must be written first, immediately followed by the high byte. Reading or writing to these registers without following these requirements will cause errors.

I²C Write Transaction

A Write transaction consists of a START, CHIP-ADDRESSWRITE, REGISTER-ADDRESS WRITE, DATA BYTE(S), and STOP. Following each byte (9TH clock pulse) the slave places an ACKNOWLEDGE/NOT- ACKNOWLEDGE (ACK/NACK) on the bus. If NACK is transmitted by the slave, the master may issue a STOP.

I²C Read Transaction

A Read transaction consists of a START, CHIP-ADDRESSWRITE, REGISTER-ADDRESS, RESTART, CHIP-ADDRESSREAD, DATA BYTE(S), and STOP. Following all but the final byte the master places an ACK on the bus (9TH clock pulse). Termination of the Read transaction is indicated by a NACK being placed on the bus by the master, followed by STOP.

The I²C bus protocol was developed by Philips (now NXP). For a complete description of the I²C protocol, please review the NXP I²C design specification.

Figure 23:
Simplified State Diagram

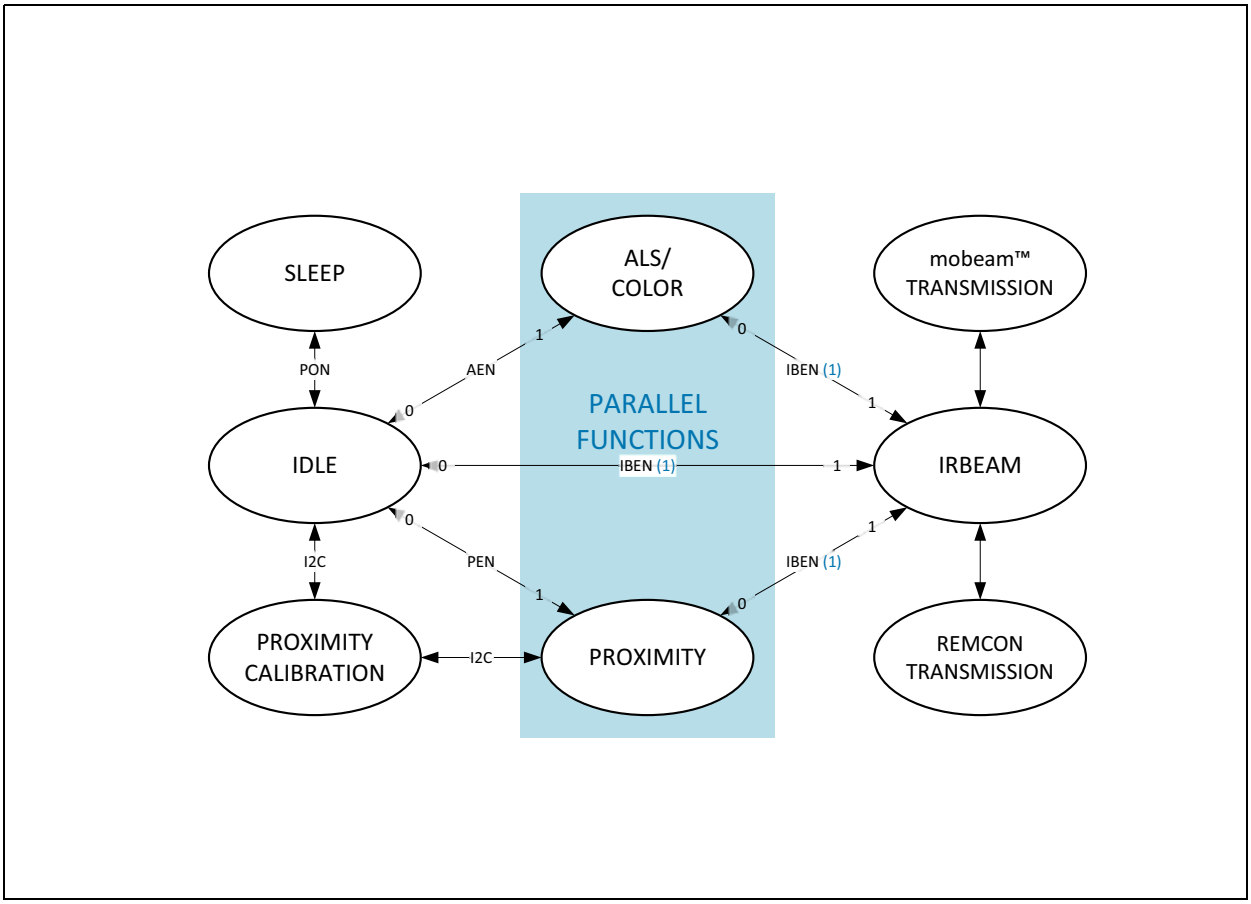
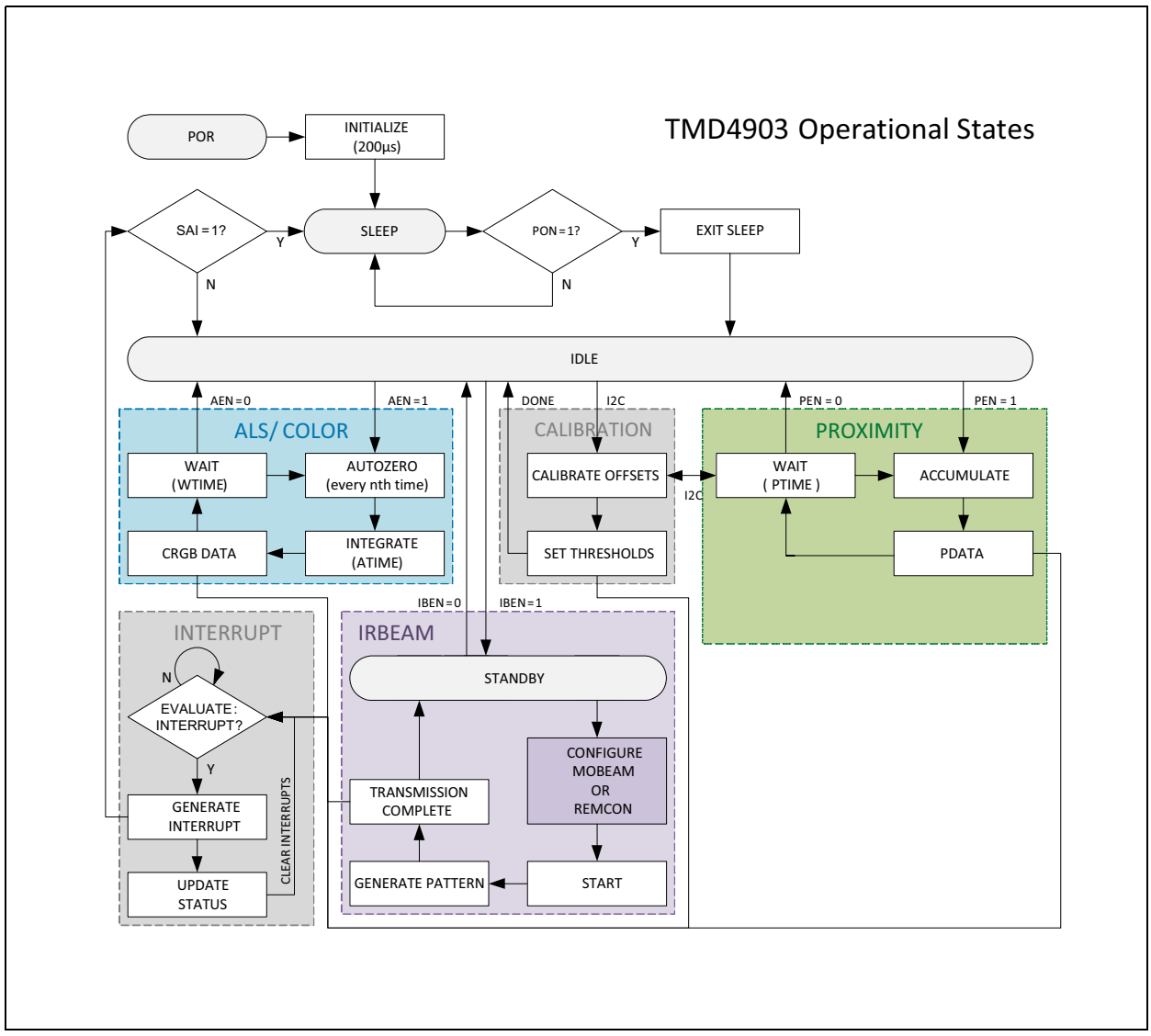


Figure 24:
Detailed State Diagram



Note(s) and/or Footnote(s):

1. While IRBeam is enabled (IBEN = 1), PROXIMITY is disabled automatically.

Detailed Description

Upon power-up, POR, the device initializes. During initialization (typically 200µs), the device will deterministically send NAK on I^2C and cannot accept I^2C transactions. All communication with the device must be delayed, and all outputs from the device must be ignored including interrupts. After initialization, the device enters the SLEEP state. In this operational state the internal oscillator and other circuitry are not active, resulting in ultra-low power consumption. If I^2C transaction occurs during this state, the I^2C core wake up temporarily to service the communication. Once the Power ON bit, PON, is enabled, the device enters the IDLE state in which the internal oscillator and attendant circuitry are active, but power consumption remains low. The first time the SLEEP state is exited and any functions are enabled (PEN | AEN | IBEN = 1) an EXIT SLEEP pause occurs followed by an immediate entry into the selected engines. If all functions are disabled
(PEN = 0 & AEN = 0 & IBEN = 0), the device returns to the IDLE state.

As depicted in Figure 23 and Figure 24, the proximity and CRGB color sensing functions operate in parallel when enabled (PEN | AEN = 1). The IRBeam pattern generator takes priority when enabled (IBEN = 1).Proximity will not function, and ALS integration only occurs while IRBeam is in standby. In addition, when proximity or calibration is requested, it will temporarily disable the proximity function. A simplified state diagram for each function is depicted in Figure 24. Each function is individually configured (e.g. Gain, ADC integration time, wait time, persistence, thresholds, etc.).

Sleep After Interrupt Operation

If Sleep After Interrupt is enabled (SAI = 1), the state machine will enter SLEEP when non-gesture interrupts occur. However for IRBeam, the state machine remains active to continue to support this function. Entering SLEEP does not automatically change any of the register settings (E.g. PON bit is still high, but the normal operational state is over-ridden by SLEEP state). SLEEP state is terminated when the SAI bit is cleared.

Register Description

The device is controlled and monitored by registers accessed through the I^2C serial interface. These registers provide for a variety of control functions and can be read to determine results of the ADC conversions. The register set is summarized in Figure 25.

Figure 25:
Control Register Map

Address	Register Name	R/W	Register Function	Reset Value
0x00 – 0x7F	RAM	R/W	Volatile Storage for Pattern data	0x00
0x80	ENABLE	R/W	Enables states and interrupts	0x00
0x81	ATIME	R/W	ADC integration time	0xFF
0x82	PTIME	R/W	Proximity sample time	0x00
0x83	WTIME	R/W	ALS wait time	0xFF
0x84	AILTL	R/W	ALS interrupt low threshold low byte	0x00
0x85	AILTH	R/W	ALS interrupt low threshold high byte	0x00
0x86	AIHTL	R/W	ALS interrupt high threshold low byte	0x00
0x87	AIHTH	R/W	ALS interrupt high threshold high byte	0x00
0x88	PILTL	R/W	Proximity interrupt low threshold low byte	0x00
0x89	PILTH	R/W	Proximity interrupt high threshold high byte	0x00
0x8A	PIHTL	R/W	Proximity interrupt low threshold low byte	0x00
0x8B	PIHTH	R/W	Proximity interrupt high threshold high byte	0x00
0x8C	PERS	R/W	ALS & Proximity interrupt persistence filters	0x00
0x8D	CFG0	R/W	Configuration register zero	0xA0
0x8E	PGCFG0	R/W	Proximity pulse width and count	0x4F
0x8F	PGCFG1	R/W	Proximity gain and LED current	0x80
0x90	CFG1	R/W	Configuration register one	0x00
0x91	REVID	R	Revision ID	0x22
0x92	ID	R	Device ID	0xB8
0x93	STATUS	R	Device status register one	0x00
0x94	CDATAL	R	Clear ADC low data register	0x00
0x95	CDATAH	R	Clear ADC high data register	0x00
0x96	RDATAL	R	Red ADC low data register	0x00

Address	Register Name	R/W	Register Function	Reset Value
0x97	RDATAH	R	Red ADC high data register	0x00
0x98	GDATAL	R	Green ADC low data register	0x00
0x99	GDATAH	R	Green ADC high data register	0x00
0x9A	BDATAL	R	Blue ADC low data register	0x00
0x9B	BDATAH	R	Blue ADC high data register	0x00
0x9C	PDATAL	R	Proximity ADC low data register	0x00
0x9D	PDATAH	R	Proximity ADC high data register	0x00
0x9E	STATUS2	R	Additional device status	0x00
0x9F	CFG2	R/W	Configuration register two	0x04
0xA0	ICONFIG	R/W	IRBeam configuration register one	0x00
0xA1	ICONFIG2	R/W	IRBeam configuration register two	0x00
0xA2	ISNL	R/W	IRBeam symbol loops	0x00
0xA3	ISOFF	R/W	IRBeam delay between symbol loops	0x00
0xA4	IPNL	R/W	IRbeam packet loops	0x00
0xA5	IPOFF	R/W	IRBeam delay between packet loops	0x00
0xA6	IBT	R/W	IRBeam time period	0x00
0xA7	ISLEN	R/W	IRBeam symbol length	0x00
0xA8	ISTATUS	R	IRBeam status	0x00
0xA9	ISTART	R/W	IRBeam start transmission	0x00
0xAB	CFG3	R/W	Configuration register three	0x00
0xAC	CFG4	R/W	Configuration register four	0x07
0xAD	CFG5	R/W	Configuration register five	0x08
0xB3	STATUS3	R	Status register three	0x00
0xBC	CONTROL	R/W	Control register	0x00
0xBD	AUXID	R	Auxiliary ID	0x00
0xC0	OFFSETNL	R/W	North channel offset low byte	0x00
0xC1	OFFSETNH	R/W	North channel offset high byte	0x00
0xC2	OFFSETSL	R/W	South channel offset low byte	0x00
0xC3	OFFSETSH	R/W	South channel offset high byte	0x00
0xC4	OFFSETWL	R/W	West channel offset low byte	0x00

Address	Register Name	R/W	Register Function	Reset Value
0xC5	OFFSETWH	R/W	West channel offset high byte	0x00
0xC6	OFFSETEL	R/W	East channel offset low byte	0x00
0xC7	OFFSETEH	R/W	East channel offset high byte	0x00
0xD6	AZ_CONFIG	R/W	Configure CRGB autozero frequency	0xFF
0xD7	CALIB	R/W	Start offset calibration	0x00
0xD8	CALIBCFG0	R/W	Calibration configuration register zero	0x44
0xD9	CALIBCFG1	R/W	Calibration configuration register one	0x0C
0xDD	INTENAB	R/W	Interrupt enable	0x00
0xDE	INCLEAR	R/W	Interrupt clear	0x00

Enable Register (ENABLE 0x80)

Enable has fields that power on the device and enable the functions. Before enabling any functions, all of the bits associated with each function must be set. Changing control register values while operating may result in invalid results.

Figure 26:
Enable Register

7	6	5	4	3	2	1	0
IBEN	Reserved	PIEN	AIEN	WEN	PEN	AEN	PON

Field	Bits	Description
IBEN	7	**IRBeam Enable.** When asserted, the LED driver pin (LDR) is controlled by the IRBeam state machine. Proximity is suppressed. ALS continues in the background except when IBUSY = 1 (ISTATUS register).
Reserved	6	**Reserved.** Bit must be set to 0.
PIEN	5	**Proximity Interrupt Enable.** When asserted permits proximity interrupts to be generated, subject to the proximity thresholds and persistence filter.
AIEN	4	**ALS Interrupt Enable.** When asserted permits ALS interrupts to be generated, subject to the ALS thresholds and persistence filter.
WEN	3	**Wait Enable.** This bit activates the wait feature. Writing a 1 activates the wait timer. Writing a 0 disables the wait timer.
PEN	2	**Proximity Enable.** This bit activates the proximity function. Writing a 1 enables proximity. Writing a 0 disables proximity.
AEN	1	**ALS Enable.** This bit activates the ALS/Color functionality. Writing a 1 enables ALS/Color. Writing a 0 disables ALS/Color.
PON	0	**Power ON.** This bit activates the internal oscillator to permit the timers and ADC channels to operate. Writing a 1 activates the oscillator. Writing a 0 disables the oscillator and clears IBEN, PEN, and AEN. Only set this bit after all other registers have been initialized by the host.

ALS Integration Time Register (ATIME 0x81)

Figure 27:
ALS Integration Time Register

7	6	5	4	3	2	1	0
ATIME							

Field	Bits	Description		
ATIME	7:0	**ALS Integration Time.** Sets the internal integration time of ALS/Color analog to digital converters in increments of 2.78ms. The power on reset value is 0xFF. The ADC maximum count (or saturation) value depends on the integration time. It is the lesser of either: 65535 (16-bit saturation) or The result of equation: $Count_{MAX} = 1024 \; X \; CYCLES$		
		VALUE	**INTEGRATION TIME**	**MAX COUNTS**
		0xFF	2.78ms	1024
		0xF6	27.8ms	10240
		0xDC	100ms	36864
		…	*2.78ms X (256 - ATIME)*	…
		0xC0	178ms	65535
		0x00	711ms	65535

Proximity Sample Time Register (PTIME 0x82)

Figure 28:
Proximity Sample Time Register

7	6	5	4	3	2	1	0
PTIME							

Field	Bits	Description		
PTIME	7:0	**Proximity Sample Time.** Sets the proximity sample rate. The power on reset value is 0x00. Proximity is executed once for each sample time.		
		VALUE	**SAMPLE TIME**	**FREQUENCY**
		0x00	2.78ms	360Hz
		0x01	5.56ms	180Hz
		0x03	11.1ms	90Hz
		0x23	100ms	10Hz
		…	*2.78ms X (PTIME +1)*	*1/Proximity Sample Time*
		0xFF	711ms	1.41Hz

Wait Time Register (WTIME 0x83)

Figure 29:
Wait Time Register

7	6	5	4	3	2	1	0
WTIME							

Field	Bits	Description		
WTIME	7:0	**Wait Time.** Sets the wait time between ALS cycles. Wait mode reduces current consumption. It is set in 2.78ms increments unless the WLONG bit is asserted in which case the wait times are 12x longer. The power on reset value is 0xFF. Wait time should be configured before AEN is asserted.		
		VALUE	**WAIT TIME (WLONG=0)**	**WAIT TIME (WLONG=1)**
		0xFF	2.78ms	0.03sec
		0xDC	100ms	1.20sec
		…	*2.78ms X (256 - WTIME)*	*33.3ms X (256 - WTIME)*
		0x6A	417ms	5.00sec
		0x00	711ms	8.53sec

ALS Interrupt Threshold Registers (0x84 – 0x87)

ALS level detection uses data generated by the Clear Channel. The ALS Interrupt Threshold registers provide 16-bit values to be used as the high and low thresholds for comparison to the 16-bit CDATA values. If AIEN is enabled and CDATA is not between AILT and AIHT for the number of consecutive samples specified in APERS an interrupt is asserted on the interrupt pin.

Figure 30:
ALS Interrupt Threshold Registers

Field	Register	Bits	Description
AILT	0x84	7:0	ALS low threshold low byte
	0x85	15:8	ALS low threshold high byte
AIHT	0x86	7:0	ALS high threshold low byte
	0x87	15:8	ALS high threshold high byte

Proximity Interrupt Threshold Registers (0x88 – 0x8B)

The Proximity Interrupt Threshold Registers set the high and low trigger points for the comparison function which generates an interrupt. If PDATA, the value generated by proximity channel, crosses from above to below the lower threshold or from below to above the upper threshold, an interrupt may be signaled to the host processor. Interrupt generation is subject to the value set in persistence filter (PPERS).

Figure 31:
Proximity Interrupt Threshold Registers

Field	Register	Bits	Description
PILT	0x88	7:0	Proximity low threshold low byte
	0x89	15:8	Proximity low threshold high byte
PIHT	0x8A	7:0	Proximity high threshold low byte
	0x8B	15:8	Proximity high threshold high byte

Interrupt Persistence Register (PERS 0x8C)

Figure 32:
Interrupt Persistence Register

7	6	5	4	3	2	1	0
PPERS				APERS			

Field	Bits	Description	
PPERS	7:4	**Proximity Interrupt Persistence.** Defines a filter for the number of consecutive occurrences that PDATA must remain outside the threshold range between PILT and PIHT before an interrupt is generated. Any sample that is inside the threshold range resets the counter to 0.	
		VALUE	**CONSECUTIVE OCCURENCES OUT OF RANGE**
		0	Every proximity cycle generates an interrupt
		1	Generate interrupt after every occurrence.
		2	Generate interrupt after 2 occurrences.
		...	Generate interrupt after *PPERS* occurrences.
		15	Generate interrupt after 15 occurrences.
APERS	3:0	**ALS Interrupt Persistence.** Defines a filter for the number of consecutive occurrences that CDATA must remain outside the threshold range between AILT and AIHT before an interrupt is generated. Any sample that is inside the threshold range resets the counter to 0.	
		VALUE	**CONSECUTIVE OCCURENCES OUT OF RANGE**
		0	Every ALS cycle generates an interrupt
		1	Generate interrupt after every occurrence.
		2	Generate interrupt after 2 occurrences.
		3	Generate interrupt after 3 occurrences.
		4	Generate interrupt after 5 occurrences.
		5	Generate interrupt after 10 occurrences.
		…	Generate interrupt after *5 X (APERS -3)* occurrences.
		14	Generate interrupt after 55 occurrences.
		15	Generate interrupt after 60 occurrences.

Configuration Register Zero (CFG0 0x8D)

Figure 33:
Configuration Register Zero

7	6	5	4	3	2	1	0
Reserved		LOWPOWER_IDLE	Reserved		WLONG	RAM_BANK	

Field	Bits	Description	
Reserved	7:6	Reserved	
LOWPOWER_IDLE	5	**Low Power Idle.** When asserted, the device will run in a low power mode if all functions are in wait states or disabled.	
Reserved	4:3	Reserved	
WLONG	2	**Wait Long Enable.** When asserted, the wait cycles are increased by a factor 12x.	
RAM_BANK	1:0	**RAM Bank Selection.** Specifies the RAM bank to access for IRBeam.	
		VALUE	**RAM BANK ACCESS**
		0	Ram Bank 0 (lower 128 bytes)
		1	Ram Bank 1 (upper 128 bytes)
		2	Access is given to the 16 words at 0xB0…0xBF.
		3	

Proximity Configuration Register Zero (PGCFG0 0x8E)

PGCFG0 has fields that set the amount of time the LDR driver is sinking current during a proximity pulse and set the maximum number of pulses for each proximity sample.

Figure 34:
Proximity Configuration Register Zero

7	6	5	4	3	2	1	0
PGPULSE_LEN		PPULSE					

Field	Bits	Description	
PGPULSE_LEN	7:6	**Proximity Pulse Length.** Sets the LED-ON pulse width during a Proximity Pulse.	
		VALUE	**LED ON**
		0	4µs
		1	8µs
		2	16µs
		3	32µs
PPULSE	5:0	**Proximity Pulse Count.** Specifies the maximum number of Proximity pulses to be generated on LDR. The pulse count can be set between 1 and 64 pulses. The number of pulses is equal to the PPULSE value plus 1.	

Proximity Configuration Register One (PGCFG1 0x8F)

PGCFG1 has fields that set the electrical gain of the proximity response and set the LED drive current during pulses.

Figure 35:
Proximity Configuration Register One

7	6	5	4	3	2	1	0
PGGAIN		Reserved	PGLDRIVE				Reserved

Field	Bits	Description	
PGGAIN	7:6	Proximity Gain Control.	
		VALUE	**GAIN VALUE**
		0	1x Gain
		1	2x Gain
		2	4x Gain
		3	8x Gain
Reserved	5	**Reserved.** Bit must be set to 0.	
PGLDRIVE	4:1	**Proximity LED Drive Strength.** Configures nominal LED current linearly in steps of 20mA (actual current depends on factory-configuration of LED drive strength).	
		VALUE	**LED STRENGTH**
		0	10mA
		1	30mA
		2	50mA
		…	*10mA + (20mA * PGLDRIVE)*
		14	290mA
		15	310mA
Reserved	0	**Reserved.** Bit must be set to 0.	

Configuration Register One (CFG1 0x90)

CFG1 has fields that enable or disable the saturation interrupts for Proximity and ALS and set the electrical gain of the ALS response.

Figure 36:
Configuration Register One

7	6	5	4	3	2	1	0
PGSIEN	ASIEN	Reserved				AGAIN	

Field	Bits	Description	
PGSIEN	7	**Proximity Saturation Interrupt Enable.** When asserted permits proximity saturation interrupts to be generated.	
ASIEN	6	**ALS Saturation Interrupt Enable.** When asserted permits ALS saturation interrupts to be generated.	
Reserved	5:2	**Reserved.** Bits must be set to 0.	
AGAIN	1:0	ALS and Color Gain Control.	
		FIELD VALUE	**CRGB GAIN VALUE**
		0	1x Gain
		1	4x Gain
		2	16x Gain
		3	64x Gain

Revision ID Register (REVID 0x91)

Figure 37:
Revision ID Register

7	6	5	4	3	2	1	0
Reserved						REV_ID	

Field	Bits	Description
Reserved	7:3	**Reserved.** Default value is 00100.
REV_ID	2:0	Wafer die revision level. Default value is 010.

ID Register (ID 0x92)

Figure 38:
ID Register

7	6	5	4	3	2	1	0
ID						Reserved	

Field	Bits	Description
ID	7:2	Device Identification = 101110
Reserved	1:0	**Reserved.** Default value is 00.

Status Register (STATUS 0x93)

The read-only Status Register provides the status of the device.

Figure 39:
Status Register

7	6	5	4	3	2	1	0
ASAT	PGSAT	PINT	AINT	IINT	Reserved	CINT	Reserved

Field	Bits	Description
ASAT	7	**ALS Saturation.** If ASIEN is set, indicates ALS saturation. Check the STATUS2 register to differentiate between analog or digital saturation.
PGSAT	6	**Proximity Saturation.** If PGSIEN is set, indicates analog saturation during a previous proximity cycle. Check the STATUS2 register to differentiate between ambient or reflected light saturation.
PINT	5	**Proximity Interrupt.** If PIEN is set, indicates that a proximity detect or release event that met the programmed proximity thresholds (PILT or PIHT) and persistence (PPERS) occurred.
AINT	4	**ALS Interrupt.** If ASIEN is set, indicates that an ALS event that met the programmed ALS thresholds (AILT or AIHT) and persistence (APERS) occurred.
IINT	3	**IRBeam Interrupt.** If IIEN is set, indicates that the device is asserting an end-of-transmission interrupt after transmitting a block of data. Bit is mirrored in the ISTATUS register.
Reserved	2	Reserved.
CINT	1	**Calibration Interrupt.** Indicates that either calibration is finished or that one of certain events have occurred during normal operation. If each function is enabled, CINT will be asserted if too many zeroes occur too often in a period of samples, if the proximity baseline has decreased, or if at least one offset register has been adjusted. Check the CALIBSTAT register to identify the triggering event(s).
Reserved	0	Reserved.

CRGB Data Registers (0x94 – 0x9B)

Red, green, blue, and clear data are stored as 16-bit values. The read sequence must read byte pairs (low followed by high) starting on an even address boundary (0x94, 0x96, 0x98, or 0x9A) inside the CRGB Data Register block. In addition, reading the Clear channel data low byte (0x94) latches all 8 data bytes. Reading these 8 bytes consecutively (0x94 - 0x9A) ensures that the data is concurrent.

Figure 40:
CRGB Data Registers

Field	Register	Bits	Description
CDATA	0x94	7:0	Clear channel data low byte
	0x95	15:8	Clear channel data high byte
RDATA	0x96	7:0	Red channel data low byte
	0x97	15:8	Red channel data high byte
GDATA	0x98	7:0	Green channel data low byte
	0x99	15:8	Green channel data high byte
BDATA	0x9A	7:0	Blue channel data low byte
	0x9B	15:8	Blue channel data high byte

Proximity Data Registers (0x9C – 0x9D)

Proximity data is stored as a 14-bit value (two bytes). PDATA has a two-byte latch like 16-bit fields. Reading the low byte first latches the high byte.

Proximity detection uses an Automatic Pulse Control (APC) mechanism that adjusts the number of pulses per measurement based on the magnitude of the reflected IR signal. As the magnitude of the signal increases, the number of pulses decreases. Proximity detection uses a 10-bit ADC that is extended to a 14-bit dynamic range for PDATA using the following formula:

$PDATA = ADC_{value} \times (16 / proximity\ pulses)$

PDATA is the average response of the non-masked proximity photodiodes. If one or more photodiodes are masked (CFG2 register 0x9F), the proximity response will remain the same since it is an average of the active photodiodes. PDATA is therefore proportional to the reflected energy per pulse, independent of the number of pulses used.

Figure 41:
Proximity Data Register

Field	Register	Bits	Description
PDATA	0x9C	7:0	Proximity data low byte
	0x9D	13:8	Proximity data high byte

Status Register Two (STATUS2 0x9E)

Figure 42:
Status Register Two

7	6	5	4	3	2	1	0
PVALID	AVALID	Reserved	ASAT_ DIGITAL	ASAT_ ANALOG	PGSAT_ ADC	PGSAT_ REFLECTIVE	PGSAT_ AMBIENT

Field	Bits	Description
PVALID	7	**Proximity Valid.** Indicates that the proximity state has completed a cycle since either an assertion of PEN or the last readout of PDATA.
AVALID	6	**ALS Valid.** Indicates that the ALS state has completed a cycle since either an assertion of AEN or the last readout of at least one the CDATAL register.
Reserved	5	Reserved.
ASAT_DIGITAL	4	**ALS Digital Saturation.** Indicates that the maximum counter value has been reached. Maximum counter value depends on integration time set in the ATIME register.
ASAT_ANALOG	3	**ALS Analog Saturation.** Indicates that the intensity of ambient light has exceeded the maximum integration level for the ALS analog circuit.
PGSAT_ADC	2	**Proximity ADC Saturation.** Indicates that the maximum ADC value has occurred.
PGSAT_REFLECTIVE	1	**Proximity Reflective Saturation.** Indicates that the intensity of reflected light has exceeded the maximum integration level for the proximity analog circuit.
PGSAT_AMBIENT	0	**Proximity Ambient Saturation.** Indicates that the intensity of ambient light has exceeded the maximum integration level for the proximity analog circuit.

Configuration Register Two (CFG2 0x9F)

Figure 43:
Configuration Register Two

7	6	5	4	3	2	1	0
PMASK_E	PMASK_W	PMASK_S	PMASK_N	AMASK	Reserved		

Field	Bits	Description
PMASK_E	7	**Proximity Mask East.** Writing a 1 disables the East photodiode.
PMASK_W	6	**Proximity Mask West.** Writing a 1 disables the West photodiode.
PMASK_S	5	**Proximity Mask South.** Writing a 1 disables the South photodiode.
PMASK_N	4	**Proximity Mask North.** Writing a 1 disables the North photodiode.
AMASK	3	**ALS Mask.** Writing a 1 reduces the ALS gain by a factor of the ALS photodiode pixels. Only the center 2x2 array of pixels remains enabled out of the 4x4 array. Reduces ALS sensitivity for measurement of maximum ambient light levels.
Reserved	2:0	Reserved.

IRBeam Configuration Register (ICONFIG 0xA0)

Figure 44:
IRBeam Configuration Register

7	6	5	4	3	2	1	0
Reserved		IIEN	SLEW	Reserved	ISQZT		

Field	Bits	Description	
Reserved	7:6	Reserved	
IIEN	5	**IRBeam Interrupt Enable.** When asserted permits IRBeam interrupts to be generated.	
SLEW	4	**Slew Rate Control.** Must be set to 1. Slew rate is used to maintain LED pulse symmetry.	
Reserved	3	Reserved	
ISQZT	2:0	**IRBeam Symbol Quiet Zone Time.** Defines the delay between symbols as a multiple of fundamental bit-times (IBT), calculated as follows: $t_{ISQZT} = n_{ISQZT} X t_{IBT}$	
		VALUE	**QUIET ZONE DURATION**
		0	0 bit-times (Not activated)
		1	5 bit-times
		2	9 bit-times
		…	$n_{ISQZT} = 2^{ISQZT+1} + 1$
		6	129 bit-times
		7	257 bit-times

IRBeam Configuration Register Two (ICONFIG2 0xA1)

Figure 45:
IRBeam Configuration Register Two

7	6	5	4	3	2	1	0
Reserved		IINVERT	IOUTPUT		IRCDCMODE	IDUTY	

Field	Bits	Description	
Reserved	7:6	Reserved.	
IINVERT	5	**IRBeam Invert.** If asserted, the IRBeam output is inverted.	
IOUTPUT	4:3	**IRBeam Output Pin.** Define which output pin used for IRBeam.	
		VALUE	**IRBEAM OUTPUT PIN**
		0	LDR
		1	LDR (digital mode)
		2	INT
		3	GPIO
IRCDCMODE	2	IRBeam Remote Control DC Mode. If asserted, the pattern is transmitted in DC mode without carrier modulation. Timing is still defined by the IBT register.	
IDUTY	1:0	**IRBeam Duty Cycle.** Define the IRBeam duty cycle.	
		VALUE	**IRBEAM DUTY CYCLE**
		0	50%
		1	37.5%
		2	25%
		3	12.5%

IRBeam Symbol Looping Register (ISNL 0xA2)

Figure 46:
IRBeam Symbol Looping Register

7	6	5	4	3	2	1	0
ISNL							

Field	Bits	Description
ISNL	7:0	**IRBeam Symbol Looping.** Sets the number of times that a Symbol is repeated in each Packet. A Symbol is a single IRBeam data transmission. The following equation describes the number of Symbols per Packet as a function of ISNL: $n_{Symbol\ Repetitions} = ISNL + 1$

IRBeam Inter-Symbol OFF Register (ISOFF 0xA3)

Figure 47:
IRBeam Inter-Symbol OFF Register

7	6	5	4	3	2	1	0
ISOFF							

Field	Bits	Description
ISOFF	7:0	**Inter-Symbol Delay Time.** Defines the delay (LED OFF) between Symbols within Packets, t_{ISDT}, which can range from 4.25µs to 127.75µs. The minimum permitted register value is 8. The following equation describes the time delay as a function of ISOFF and IBT: $t_{ISDT} = [(2\ X\ ISOFF) + 1]\ X\ t_{IBT}$

IRBeam Packet Looping Register (IPNL 0xA4)

Figure 48:
IRBeam Packet Looping Register

7	6	5	4	3	2	1	0
IPNL							

Field	Bits	Description
IPNL	7:0	**IRBeam Packet Looping.** Sets the number of times that a Packet is repeated. Each packet consists of repeated transmission of a Symbol. The following equation describes the number of Packet repetitions as a function of IPNL: $n_{Packet\ Repetitions} = IPNL + 1$

IRBeam Inter-Packet OFF Register (IPOFF 0xA5)

Figure 49:
IRBeam Inter-Packet OFF Register

7	6	5	4	3	2	1	0
IPOFF							

Field	Bits	Description
IPOFF	7:0	**Inter-Packet Delay Time.** Defines the delay (LED OFF) between Packet repetitions, t_{IPDT}, which can range from 10µs to 255.25µs. The minimum permitted register value is 8. The following equation describes the time delay as a function of IPOFF and IBT: $t_{ISDT} = [(2\ X\ IPOFF) + 1]\ X\ t_{IBT}$

IRBeam Bit Time Register (IBT 0xA6)

Figure 50:
IRBeam Bit Time Register

7	6	5	4	3	2	1	0
Reserved		IBT					

Field	Bits	Description
Reserved	7:6	Reserved.
IBT	5:0	**IRBeam Bit Time.** Defines the fundamental IRBeam bit-time, t_{IBT}, which can range from 0.25µs to 64µs. The IRBeam bit time is set by the following equation: $t_{IBT} = (IBT + 1)\ X\ 0.25\mu s$

IRBeam Symbol Length Register (ISLEN 0xA7)

Figure 51:
IRBeam Symbol Length Register

7	6	5	4	3	2	1	0
ISLEN							

Field	Bits	Description
ISLEN	7:0	**IRBeam Symbol Length.** Defines the length of the IRBeam Symbol in bytes. The minimum length is 2 bytes, meaning the minimum register value is 1. The following equation describes the length of the Symbol in bytes: $I_{Symbol} = ISLEN + 1$

IRBeam Status Register (ISTATUS 0xA8)

Figure 52:
IRBeam Status Register

7	6	5	4	3	2	1	0
Reserved						IINT	IBUSY

Field	Bits	Description
Reserved	7:2	Reserved.
IINT	1	**IRBeam Interrupt.** If IIEN is set, indicates that the device is asserting an end-of-transmission interrupt after transmitting a block of data. Bit is mirrored in the STATUS register.
IBUSY	0	**IRBeam Busy.** Indicates an IRBeam transmission is in progress.

IRBeam Start Register (ISTART 0xA9)

Figure 53:
IRBeam Start Register

7	6	5	4	3	2	1	0
Reserved						ISTARTREMCON	ISTARTMOBEAM

Field	Bits	Description
Reserved	7:2	Reserved.
ISTARTREMCON	1	**IRBeam Start Remote Control.** Write 1 to start the remote control machine, executing from address 0. Transmission can be stopped by writing a 0 to this bit.
ISTARTMOBEAM	0	**IRBeam Start mobeam.** Write 1 to start a mobeam transmission. Transmission can be stopped by writing a 0 to this bit.

Configuration Register Three (CFG3 0xAB)

Figure 54:
Configuration Register Three

7	6	5	4	3	2	1	0
Reserved	LTF_USEPROX	Reserved	SAI	Reserved			

Field	Bits	Description			
Reserved	7	**Reserved.**			
LTF_USEPROX	6	**Use Proximity Photodiodes for ALS Measurement.** Connects the IR-sensitive proximity photodiodes to the ALS engine in order to collect ALS data in the IR band. The data registers contain the following channel data depending on the LTF_USEPROX setting.			
		16-bit Output Registers		**LTF_USEPROX**	
		High	**Low**	**0**	**1**
		0x95	0x94	Clear	North
		0x97	0x96	Red	South
		0x99	0x98	Green	West
		0x9B	0x9A	Blue	East
Reserved	5	**Reserved.**			
SAI	4	**Sleep After Interrupt.** Powers down the device at the end of a proximity/ALS cycle if an interrupt has been generated. Note that SAI does not modify any register bits directly, it rather uses the interrupt signal to turn off the oscillator. The only way to "wake up" the device from SAI-sleep is by clearing the SAI_ACTIVE flag.			
		PON	**SAI**	**INT (Low Active)**	**Oscillator**
		0			Off
		1	0		On
		1	1	1	On
		1	1	0	Off (sleep after interrupt)
Reserved	3:0	**Reserved.**			

Configuration Register Four (CFG4 0xAC)

Figure 55:
Configuration Register Four

7	6	5	4	3	2	1	0
ALS_INT_ DIRECT	ALS_INT_ DIRECT_GPIO	PROX_INT_ DIRECT	PROX_INT_ DIRECT_GPIO	Reserved			

Field	Bits	Description
ALS_INT_DIRECT	7	**ALS Interrupt Direct.** If asserted, then the INT pin shows the ALS state directly and it is not necessary to clear the interrupt. If the CLEAR data exits the threshold range from within, the INT pin is asserted. The interrupt pin is de-asserted when the CLEAR data re-enters the threshold range. As long as the CLEAR data is within the thresholds, the INT pin is not asserted.
ALS_INT_DIRECT_GPIO	6	**ALS Interrupt Direct on GPIO Pin.** If asserted, the GPIO pin shows the ALS interrupt state directly instead of the INT pin. This function operates in the same manner otherwise as ALS_INT_DIRECT.
PROX_INT_DIRECT	5	**Proximity Interrupt Direct.** If asserted, then the INT pin shows the proximity state directly and it is not necessary to clear the interrupt. If PDATA crosses the upper threshold from below, the INT pin is asserted. The interrupt pin is only de-asserted when PDATA crosses the lower threshold from above. As long as PDATA is below the lower threshold, the INT pin is not asserted.
PROX_INT_DIRECT_GPIO	4	**Proximity Interrupt Direct on GPIO Pin.** If asserted, the GPIO pin shows the proximity interrupt state directly instead of the INT pin. This function operates in the same manner otherwise as PROX_INT_DIRECT.
Reserved	3:0	**Reserved.**

Configuration Register Five (CFG5 0xAD)

Figure 56:
Configuration Register Five

7	6	5	4	3	2	1	0
Reserved		LONG_LTFSTOP_ DISCARD_ALS	Reserved	DISABLE_IR_ CORRECTION	PROX_FILTER_ DOWNSAMPLE	PROX_FILTER_ SIZE	PROX_ FILTER

Field	Bits	Description
Reserved	7:6	**Reserved.**
LONG_LTFSTOP_DISCARD_ ALS	5	**Long Disruption Discard ALS.** Aborts ALS integration that is disrupted if the proximity state is entered (sensor field of view is obstructed) or an IRBeam transmission is executed (long disruption while LED is pulsed for an extended duration). Immediately after proximity mode is exited or IRBeam transmission is complete, a new ALS integration is started. When restarting ALS, this function ignores wait configuration, which may cause more ALS measurements to occur than expected.
Reserved	4	**Reserved.**
DISABLE_IR_CORRECTION	3	**Disable IR Correction.** Default is 1. If bit is 0, then calculate IR=(R+G+B-C)/2 and store R'=R-IR, G', B', and C' in the color DATA registers.
PROX_FILTER_ DOWNSAMPLE	2	**Proximity Filter Downsample.** If PROX_FILTER = 1, then, if asserted, PDATA and proximity interrupt check are performed only every n proximity samples. If not asserted, then proximity filtering uses a moving window: PDATA is updated every cycle and proximity interrupt is checked every cycle.
PROX_FILTER_SIZE	1	**Proximity Filter Size.** Determines the number of consecutive proximity samples to average to filter out noise. **VALUE** / **FILTER** 0 / 2 samples
PROX_FILTER	0	**Proximity Filter.** If asserted, enables proximity filter functionality. Depending on PROX_FILTER_SIZE, 2 or 4 consecutive proximity samples are averaged.

Status Register Three (STATUS3 0xB3)

Figure 57:
Status Register Three

7	6	5	4	3	2	1	0
Reserved						SAI_ACTIVE	Reserved

Field	Bits	Description
Reserved	7:2	**Reserved.**
SAI_ACTIVE	1	**Sleep-After-Interrupt Active.** If SAI is set, indicates that the oscillator has been stopped and the device is in sleep after an interrupt. SAI_ACTIVE must be cleared (CONTROL 0xBC[0]: CLEAR_SAI_ACTIVE) to clear SAI and resume chip operation.
Reserved	0	**Reserved.**

Control Register (CONTROL 0xBC)

Figure 58:
Control Register

7	6	5	4	3	2	1	0
Reserved							SAI_ACTIVE_CLEAR

Field	Bits	Description
Reserved	7:1	Reserved.
SAI_ACTIVE_CLEAR	0	**Sleep-After-Interrupt Active Clear.** If SAI is set and SAI_ACTIVE is true (an Interrupt has occurred), asserting this pin clears the SAI_ACTIVE flag and restarts the device oscillator to resume chip operation if functions are enabled.

Auxiliary ID Register (AUXID 0xBD)

Figure 59:
Auxiliary ID Register

7	6	5	4	3	2	1	0
Reserved				AUXID			

Field	Bits	Description
Reserved	7:4	Reserved.
AUXID	3:0	**Auxiliary ID.** Value is 0000.

Proximity Offset Registers (0xC0 – 0xC7)

Proximity offset values have a range of ±255 and are expressed as 9-bit two's-complement values. Do not program values outside of this range. Only the lower 9 bits are significant, but the high byte must only be programmed with values of 0x00 (indicates that the low byte has a positive value) or 0xFF (indicates that the low byte has a negative value).

Figure 60:
Proximity Offset Registers

Field	Register	Bits	Description
OFFSETN	0xC0	7:0	North channel offset low byte
	0xC1	15:8	North channel offset high byte
OFFSETS	0xC2	7:0	South channel offset low byte
	0xC3	15:8	South channel offset high byte
OFFSETW	0xC4	7:0	West channel offset low byte
	0xC5	15:8	West channel offset high byte
OFFSETE	0xC6	7:0	East channel offset low byte
	0xC7	15:8	East channel offset high byte

Autozero Configuration Register (AZ_CONFIG 0xD6)

Figure 61:
Autozero Configuration Register

7	6	5	4	3	2	1	0
AZ_NTH_ITERATION							

Field	Bits	Description	
AZ_NTH_ITERATION	7:0	**ALS Autozero Frequency.** Sets the frequency at which the device performs autozero of the ALS pulse counter.	
		VALUE	**AUTOZERO FREQUENCY**
		0	Never
		1	Every cycle
		2	Every 2 cycles
		…	Every *(AZ_NTH_ITERATION)* cycles
		253	Every 253 cycles
		254	Every 254 cycles
		255	Only once (before 1st cycle)

Calibration Register (CALIB 0xD7)

Figure 62:
Calibration Register

7	6	5	4	3	2	1	0
Reserved							START_OFFSET_CALIB

Field	Bits	Description
Reserved	7:1	Reserved.
START_OFFSET_CALIB	0	**Start Offset Calibration.** Starts the proximity offset register calibration routine. Results are stored in the Proximity Offset Registers (0xC0 – 0xC7). The CALIB_FINISHED flag is asserted when calibration is complete and an interrupt (CINT) is asserted if CIEN is set. Calibration can be stopped by writing a 0 to this field.

Calibration Configuration Register Zero (CALIBCFG0 0xD8)

Figure 63:
Calibration Configuration Register Zero

7	6	5	4	3	2	1	0
Reserved	DCAVG_ AUTO_OFFSET_ ADJUST	Reserved	ELECTRICAL_ CALIBRATION	BINSRCH_ SKIP	DCAVG_ITERATIONS		

Field	Bits	Description
Reserved	7	Reserved.
DCAVG_AUTO_OFFSET_ADJUST	6	**DC Averaging Auto Offset Adjust.** If set, then during DC averaging, whenever an ADC measurement is zero, the appropriate offset register will be decreased and the OFFSET_ADJUSTED flag is set. Note also that DC averaging is not automatically restarted when this happens, so the calculated baseline might be wrong. Software could restart averaging in this case.
Reserved	5	Reserved.
ELECTRICAL_CALIBRATION	4	**Enable Electrical Calibration.** When asserted the calibration routine will perform an internal electrical calibration to adjust the proximity offset registers to remove electrical crosstalk – there is no optical response at all for this routine. When not asserted, calibration will measure both optical and electrical crosstalk during calibration.
BINSRCH_SKIP	3	**Binary Search Skip.** When asserted the calibration routine will skip the binary search step. It is useful if zeroes are detected during the DC averaging process to manually reset the baseline and reduce the likelihood of zero counts.

Field	Bits	Description	
DCAVG_ITERATIONS	2:0	**DC Averaging Iterations.** Sets the number of proximity results during calibration that are averaged after the binary search is complete. During this period, whenever a result is zero, the appropriate offset register is automatically decremented. The default value is 4 (16 iterations).	
		VALUE	**SAMPLES**
		0	Skip
		1	2
		2	4
		…	$n_{Iterations} = 2^{DCAVG\_ITERATIONS}$
		6	64
		7	128

Calibration Configuration Register One (CALIBCFG1 0xD9)

Figure 64:
Calibration Configuration Register One

7	6	5	4	3	2	1	0
PXDCAVG_AUTO_GTHR	PROX_AUTO_OFFSET_ADJUST	Reserved		PXDCAVG_AUTO_BASELINE	PXDCAVG_BASELINE_WINDOW		

Field	Bits	Description
PXDCAVG_AUTO_GTHR	7	**Proximity Automatic Thresholds.** When asserted, GTHR_IN and GTHR_OUT are automatically written with a multiple of the PBSLN every time PBSLN changes. The multiplication factor is set in AUTO_GTHR_IN_MULT. PBSLN can only change if PXDCAVG_AUTO_BASELINE is asserted and PBSLN_MEAS is less than PBSLN.
PROX_AUTO_OFFSET_ADJUST	6	**Proximity Auto Offset Adjust.** If set, then during proximity/gesture mode, whenever an ADC measurement is zero, the appropriate offset register will be decreased. Will set the OFFSET_ADJUSTED flag if it happens.
Reserved	5:4	Reserved.
PXDCAVG_AUTO_BASELINE	3	**Proximity Automatic Baseline.** When asserted, PBSLN_MEAS is written to PBSLN whenever PBSLN_MEAS is less than PBSLN. When this happens, the BASELINE_ADJUSTED flag is raised. The default value is 1.
PXDCAVG_BASELINE_WINDOW	2:0	**Prox Baseline Averaging Window.** Sets the number of proximity samples averaged to calculate PBSLN_MEAS, which is updated at the end of each window. The default value is 16 samples.

VALUE	SAMPLES
0	Skip
1	2
2	4
…	$n_{Iterations} = 2^{PXDCAVG\_BASELINE\_WINDOW}$
6	64
7	128

Interrupt Enable Register (INTENAB 0xDD)

Figure 65:
Interrupt Enable Register

7	6	5	4	3	2	1	0
ASIEN	PGSIEN	PIEN	AIEN	IIEN	Reserved	CIEN	Reserved

Field	Bits	Description
ASIEN	7	**ALS Saturation Interrupt Enable.** When asserted permits ALS saturation interrupts to be generated. Bit is mirrored in the CFG1 register.
PGSIEN	6	**Proximity Saturation Interrupt Enable.** When asserted permits proximity saturation interrupts to be generated. Bit is mirrored in the CFG1 register.
PIEN	5	**Proximity Interrupt Enable.** When asserted permits proximity interrupts to be generated, subject to the proximity thresholds and persistence filter. Bit is mirrored in the ENABLE register.
AIEN	4	**ALS Interrupt Enable.** When asserted permits ALS interrupts to be generated, subject to the ALS thresholds and persistence filter. Bit is mirrored in the ENABLE register.
IIEN	3	**IRBeam Interrupt Enable.** When asserted permits IRBeam interrupts to be generated. Bit is mirrored in the ICONFIG register.
Reserved	2	**Reserved.** Bit must be set to 0.
CIEN	1	**Calibration Interrupt Enable.** When asserted permits calibration interrupts to be generated.
Reserved	0	Reserved.

Interrupt Clear Register (INTCLEAR 0xDE)

Figure 66:
Interrupt Clear Register

7	6	5	4	3	2	1	0
INTCLEAR_ ASAT	INTCLEAR_ PGSAT	INTCLEAR_ PINT	INTCLEAR_ AINT	INTCLEAR_ IINT	Reserved	INTCLEAR_ CINT	Reserved

Field	Bits	Description
INTCLEAR_ASAT	7	**Clear Interrupt: Analog Saturation.** Clears the analog saturation interrupt.
INTCLEAR_PGSAT	6	**Clear Interrupt: Proximity Saturation.** Clears the proximity saturation interrupt.
INTCLEAR_PINT	5	**Clear Interrupt: Proximity.** Clears the proximity interrupt.
INTCLEAR_AINT	4	**Clear Interrupt: ALS.** Clears the ALS interrupt.
INTCLEAR_IINT	3	**Clear Interrupt: IRBeam.** Clears the IRBeam interrupt.
Reserved	2	**Reserved.** Bit must be set to 0.
INTCLEAR_CINT	1	**Clear Interrupt: Calibration.** Clears the calibration interrupt.
Reserved	0	Reserved.

Application Information

Figure 67:
TMD4903 Typical Application Circuit

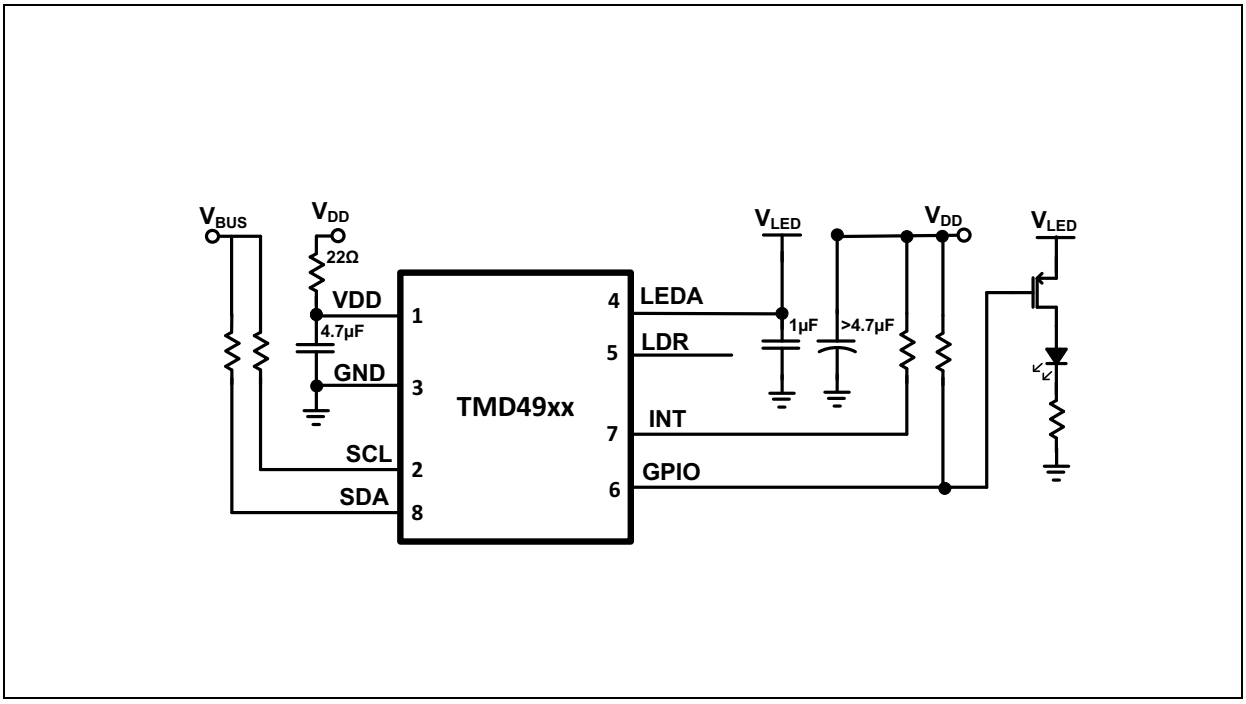
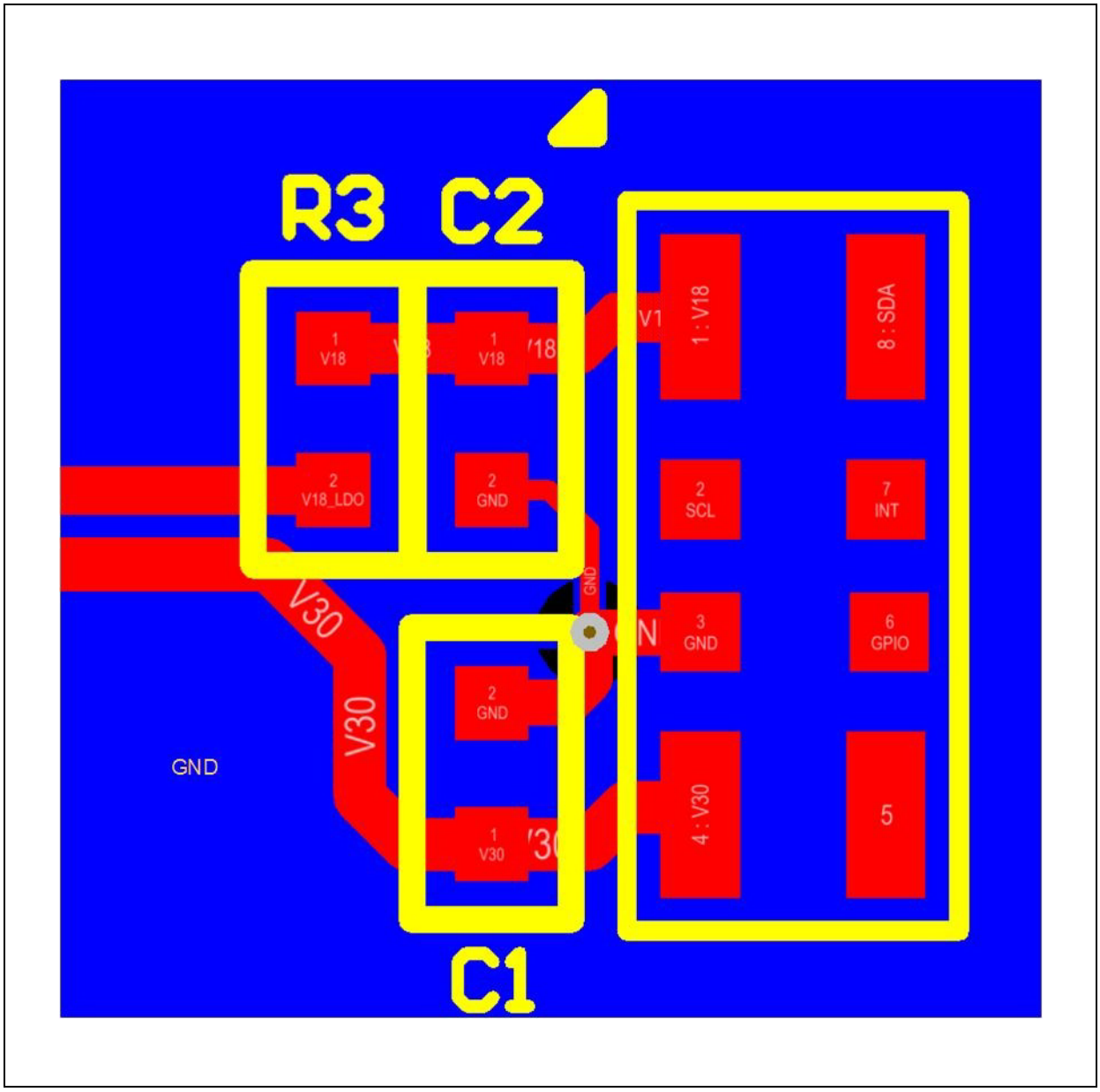


Figure 68:
TMD4903 Recommended Circuit Layout



Note(s) and/or Footnote(s):

1. For best performance, all components should be positioned as close as possible to the TMD4903. Traces and vias should be as large as possible. The proximity of the capacitors is most important.

Remote Control

General Description of RC Functionality

The TMD4903 is equipped with Remote Control functionality which is used to generate and transmit patterns over IR for electronic equipment (E.g. television, DVD, or audio receiver). Virtually all protocols can be accommodated by the specialized architecture of the Remote Control engine. The engine contains 256 bytes of pattern RAM and controls for carrier frequency, duty cycle and pattern repetition to easily create and broadcast a complete command waveform. The command waveform is output on a device pin allowing direct control of an external transistor and LED (pull-up resistor required). The integrated LED may also be used to output the IR waveform.

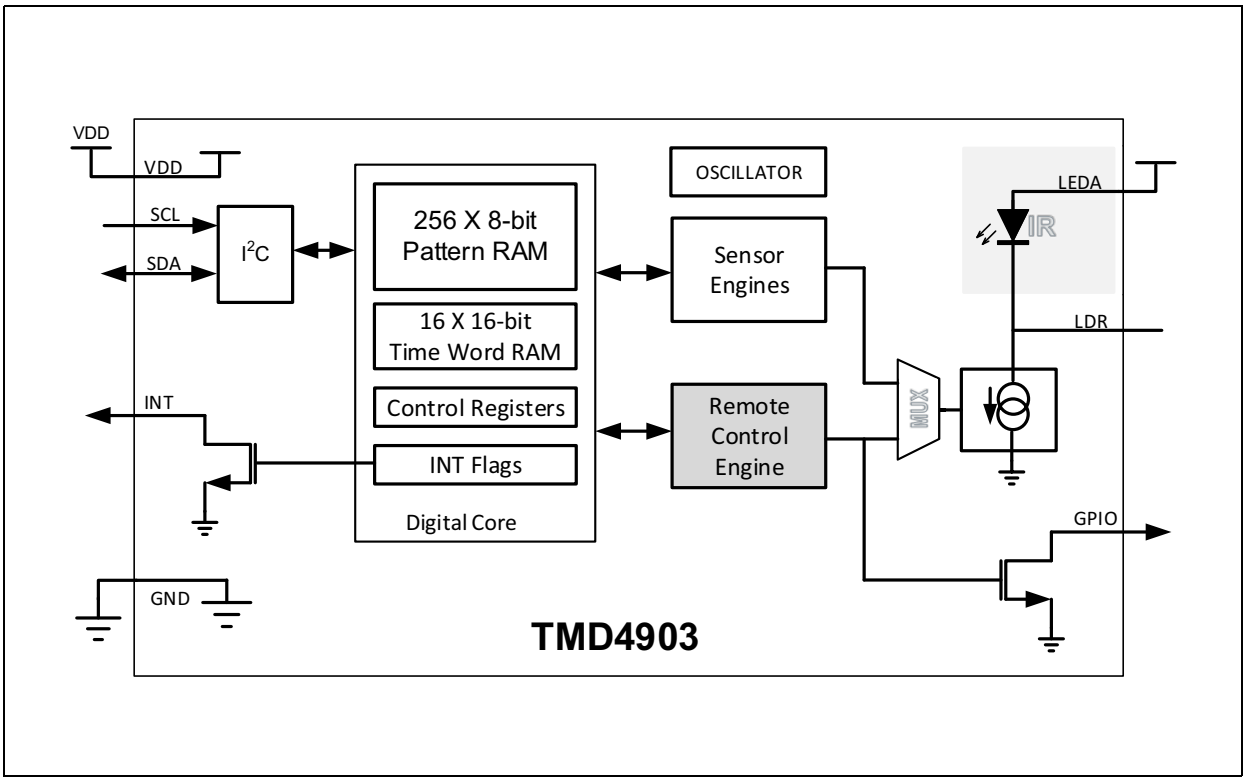
Detailed Description of RC Functionality

Remote Control functionality uses a digital core that is independent of the analog sensor operation. The logic internal to the digital core is activated when IBEN=1. In this operational mode the LDR pin is exclusively acquired; during this time sensor functionality will not operate.

Most of the functional engines are controlled by dedicated registers; however, some devices use a “shared register” scheme. For example, this device uses address space: 0xA0 to 0xAF to also control mobeam operation. Because each functional block serves a different purpose and utilizes common on-chip resources, only one may be activated at a time.

Block Diagram of Remote Control Functionality

Figure 69:
Block Diagram of RC Functionality



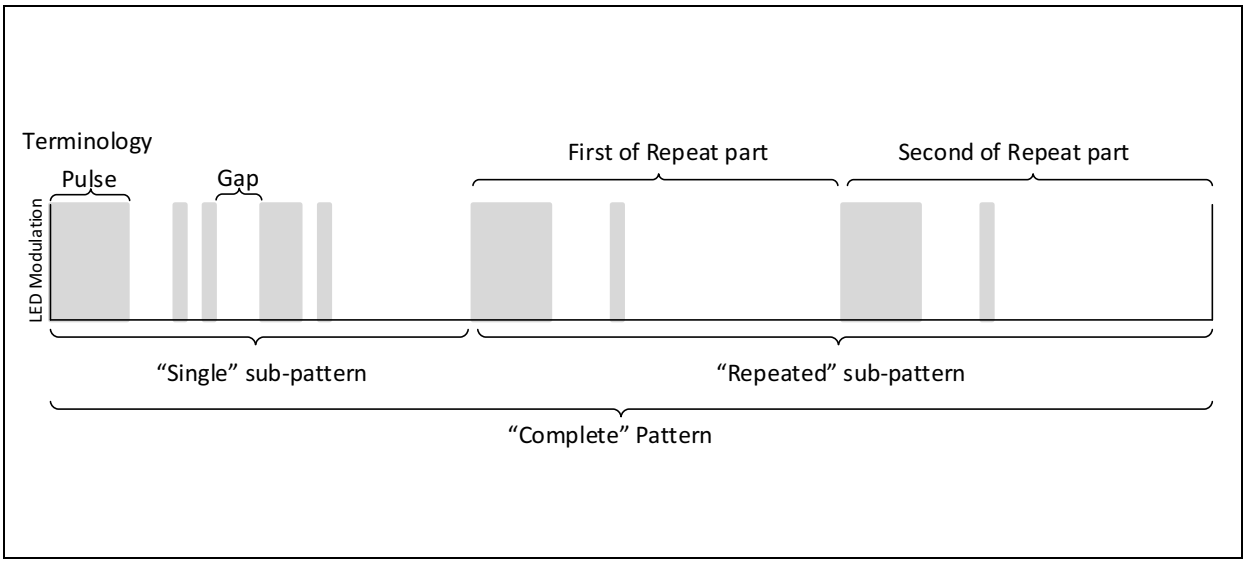
Block Diagram of RC Functionality: Resources associated with Remote Control.

There are many different remote control protocols currently in use; and to meet the multitude of requirements the remote control engine has been designed to be flexible. The remote control engine consists of four major components: Pattern RAM, Timeword RAM, control registers, and pattern output pin (or integrated LED).

Pattern RAM

The Pattern RAM is 256 bytes in length and is divided into two banks with 128 bytes each. Both banks must be used to enable all Pattern RAM. To access the Pattern RAM, write 0 or 1 to RAM_BANK (0x8D<0>). Functionally, the RAM is split into the MSB and LSB nibbles; each of which are used to index the Timeword RAM table. The MSB is used for "pulses", and the LSB is used for "gaps".

Figure 70:
Terminology of Pattern RAM



Terminology of Pattern RAM: Pulses/Gaps, and Single/Repeated/Complete Patterns are shown.

The pulse-gap pair defines when the LED is modulating or deactivated, respectively. The control logic processes the RAM locations sequentially until special operator values are encountered.

Figure 71:
Pattern RAM Table

Pattern RAM	
Address (Bank 0)	**Data (Pulse-Gap)**
0	0x0 to 0xFF
1	0x0 to 0xFF
2	0x0 to 0xFF
3	0x0 to 0xFF
~	~
255	0x0 to 0xFF

Pattern RAM: Volatile memory used for storing pattern data.

Note(s) and/or Footnote(s):

1. T_DATA = 0xFE is a special instruction. The following value in RAM becomes the start address of any repeated sub-pattern.
2. T_DATA = 0xFF is a special instruction. It identifies the end of the pattern.

There are two special values that control the flow of the pattern: Stop and Repeat-destination. A Stop is signified by the value of 0xFF loaded into a pattern ram location. The value is analogous to a *null* character at the end of a text file. Any remaining RAM after the 0xFF operator is encountered is not executed and the pattern is finished. The Repeat-destination operator is signified by a value of 0xFE followed by the start address of any repeated sub-pattern. This value is analogous to a "goto" statement. Once this value is encountered instruction pointer to the pattern RAM is changed to the address stored in the *next* pattern RAM location. These data values will not be decoded by the logic as a reference/pointer to the timeword table, that is, 0xFF will not index timeword location 15 for pulse and gap.

Timeword RAM

The Timeword RAM is a dedicated table that contains sixteen, 16-bit words which are used to set pulse and gap widths. The pulse and gap widths are described as a multiple of carrier periods, T_{CAR}. For example, if the LED must modulate for 8 carrier periods, then be off for 15 carrier periods, index 0 could be loaded with 0x0008 and index 1 could be loaded with 0x000F. A pattern RAM value of 0x01 would result in LED activation for 8 T_{CAR}s, as stored in index 0, and a LED deactivation for 15 T_{CAR}s.

Similarly to pattern RAM, the Timeword table also has a special operator. If the timeword value is zero, then whatever state the LED was in last (I.e. modulating or deactivated) will be continued into the next pulse or gap defined in pattern RAM. For example, if the RAM Pulse nibble (MSB) indexes a timeword set to 5, and the gap (LSB) nibble indexes a timeword set to 0, the LED will modulate for 5T_{CAR}s then instead of deactivating, the modulation is continued into the next pulse in pattern RAM. In this way pulses or gaps longer than 65535 T_{CAR}s can be generated.

Figure 72:
Timeword RAM Table

Timeword RAM			
T_INDEX	T_DATA	I²C Address (Bank 1)	
0	0 to 65535	0x01 8-bit MSB	0x00 8-bit LSB
1	0 to 65535	0x03 8-bit MSB	0x02 8-bit LSB
2	0 to 65535	0x05 8-bit MSB	0x04 8-bit LSB
3	0 to 65535	0x07 8-bit MSB	0x06 8-bit LSB
~	~	~	~
15	0 to 65535	0x0F 8-bit MSB	0x1E 8-bit LSB

Timeword RAM: Volatile memory used for storing 16-bit timing data.

The Timeword table is located in RAM bank two. Each 16-bit word is accessible using two byte locations: MSB bytes are stored in even addresses and LSBs are stored in odd addresses. For example, if 0x2953 is to be stored at index 0, then 0x29 is written to: bank 2, I²C address of 0x00, and 0x53 is written to bank 2, I²C address of 0x01.

Control Registers

The remote control engine has 19 fields that govern pattern timing and flow, output selection, and report status. All pertinent fields are listed in the figure below.

Figure 73:
Remote Control Registers and Fields

Register / Bit	Address	Description
ENABLE<PON>	0x80<0>	Power On
ENABLE<IBEN>	0x80<7>	IRBeam Enable
CFG0 <RAM_BANK>	0x8D<0>	RAM Bank Select
PGCFG1 <PGLDRIVE>	0x8F<4:0>	LED Drive Strength
STATUS <IINT>	0x93<3>	IRBeam Interrupt (mirrors ISTATUS<IINT>)
ICONFIG <IIEN>	0xA0<5>	IRBeam Interrupt Enable
ICONFIG2 <IINVERT>	0xA1<5>	IRBeam Polarity Inversion
ICONFIG2 <IOUTPUT>	0xA1<4:3>	Output Select
ICONFIG2 <IRCDCMODE>	0xA1<2>	DC Carrier Select
ICONFIG2 <IDUTY>	0xA1<1:0>	Duty Cycle Select
ISNL <ISNL>	0xA2<7:0>	Number of Repeated Sub-pattern Loops
ISOFF <ISOFF>	0xA3<7:0>	Pause between Sub-pattern Bursts
IPNL <IPNL>	0xA4<7:0>	Number of Complete Pattern Loops
IPOFF <IPOFF>	0xA5<7:0>	Pause between Pattern Bursts
IBT <IBT>	0xA6<5:0>	Carrier Selection Time
ISTATUS <IINT>	0xA8<1>	IRBeam Interrupt
ISTATUS <IBUSY>	0xA8<0>	IRBeam Busy
ISTART <ISTARTREMCON>	0xA9<1>	Remote Control Start Pattern Burst
INTCLEAR <INTCLEAR_IINT>	0xDE<3>	IRBeam Interrupt Clear

Pertinent Control Registers: Resources associated with Remote Control.

Carrier frequency, Duty cycle, and Pause (the delay between complete patterns) comprise the registers associated with timing. Carrier periods are selectable in 250ns increments in with register settings in the range of 8 to 255. Carrier frequencies are in the range of 16 kHz to 460 kHz. Typical carrier frequencies are listed in the table below. Protocols that do not use carriers can also be accommodated by enabling the DC Carrier Selection bit. The duty cycle of the carrier is selectable as: 50%, 37%, 25%, and 12%. Note that these duty cycles do not translate exactly to the actual LED duty cycle, depending on the external circuit. Finally, if desired, complete pattern rebursts are separated by a selectable delay of 0us to 2.55s, in 10us increments.

Figure 74:
Carrier Frequencies

Desired Frequency (kHz)	Generated Frequency (kHz)	IBT
36	36.04	111
38	38.10	105
40	40.00	100
56	56.34	71
450	444.44	9

Carrier Frequencies: Typical carrier frequencies can be reproduced to closely match the desired value.

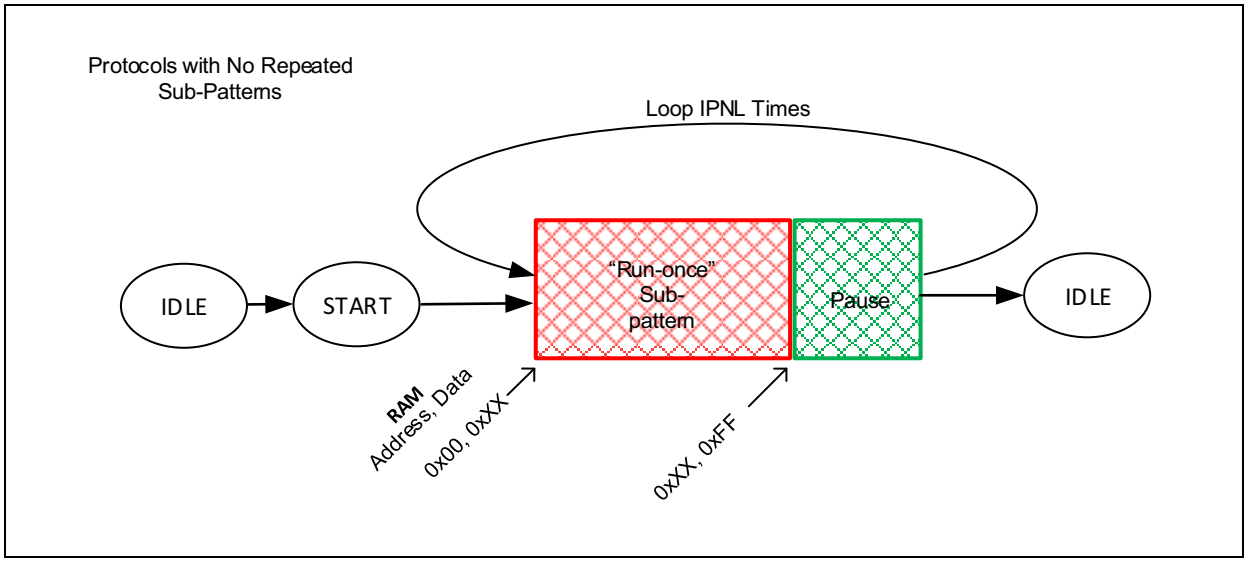
Controls associated with the output are:
Output select, Output Polarity Inversion, and LED Drive Strength. Output Select is used to choose output on the integrated LED or the GPIO pin. The polarity inversion control inverts the waveform on both the LED and the GPIO pin if enabled. The LED Drive Strength controls the current through the integrated LED which effectively sets its intensity.

Controls associated with interrupts are:
Pattern Burst Interrupt Enable, Pattern Burst Interrupt flag, Pattern Burst Interrupt Clear, Pattern Burst Interrupt Force, and Pattern Burst Busy. Following an entire pattern burst, including all repeats, loops, and delays, a pattern burst interrupt bit is set. This bit is readable from two locations: STATUS register and ISTATUS register. If the interrupt enable bit is set, then the INT pin will also activate when the burst is finished. To clear the interrupt, the host must write a zero to IRBeam Interrupt Clear (0xDE<3>). For debugging purposes the interrupt bits and pin can be forced to activate by setting the Pattern Burst Interrupt Force bit. The Pattern Burst Busy bit is automatically set whenever a pattern is actively being transmitted; it is reset once the remote control engine returns to the IDLE state.

Controls associated to define the number of complete pattern loops and sub-pattern repeats are: Number of Repeated Sub-pattern Loops and Number of Complete Pattern Loops.

As depicted below, the number of "run-once" pattern loops sets the amount of *additional* iterations, up to 254. If the register is set to 0xFF then the sub-pattern is continuously repeated until the value is changed or IBEN bit is reset.

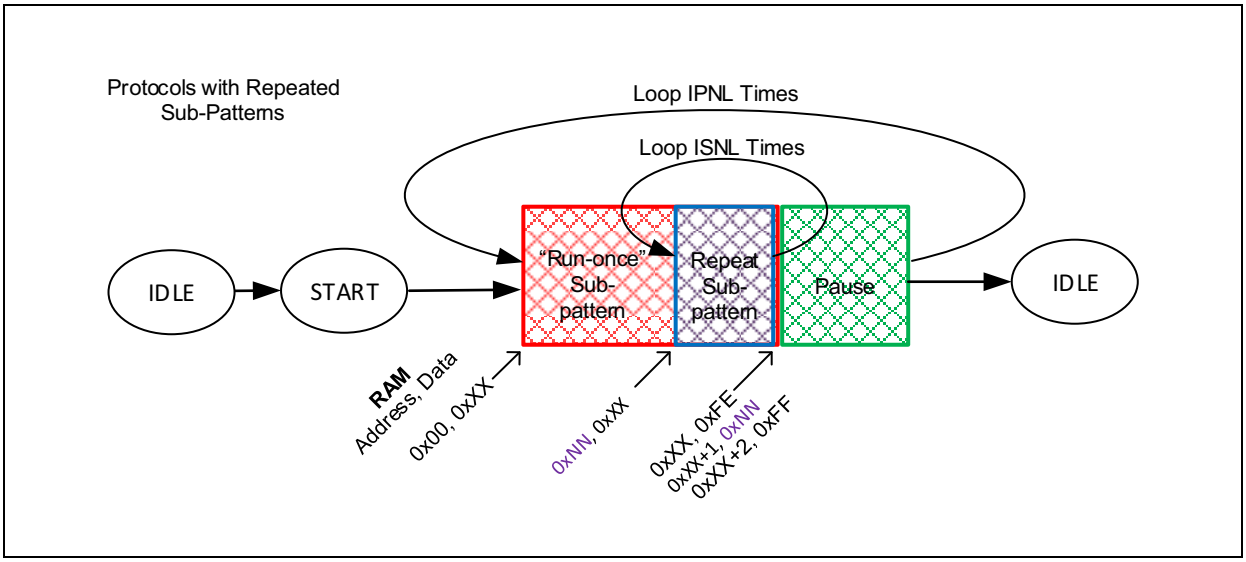
Figure 75:
Complete Pattern Loops



Complete Pattern Loops: The red box represents a "run-once" pattern. The pattern begins at pattern ram address 0x00 and bursts until the end of the pattern is encountered. The complete pattern can be reiterated 1 to 254 times, or continuously.

As depicted below, the number of repeated sub-pattern loops sets the amount of additional "repeated part" burst iterations, up to 254. If the register is set to 0xFF then the sub-pattern is continuously repeated until the value is changed or IBEN bit is reset.

Figure 76:
Number of Repeated Sub-Pattern Loops



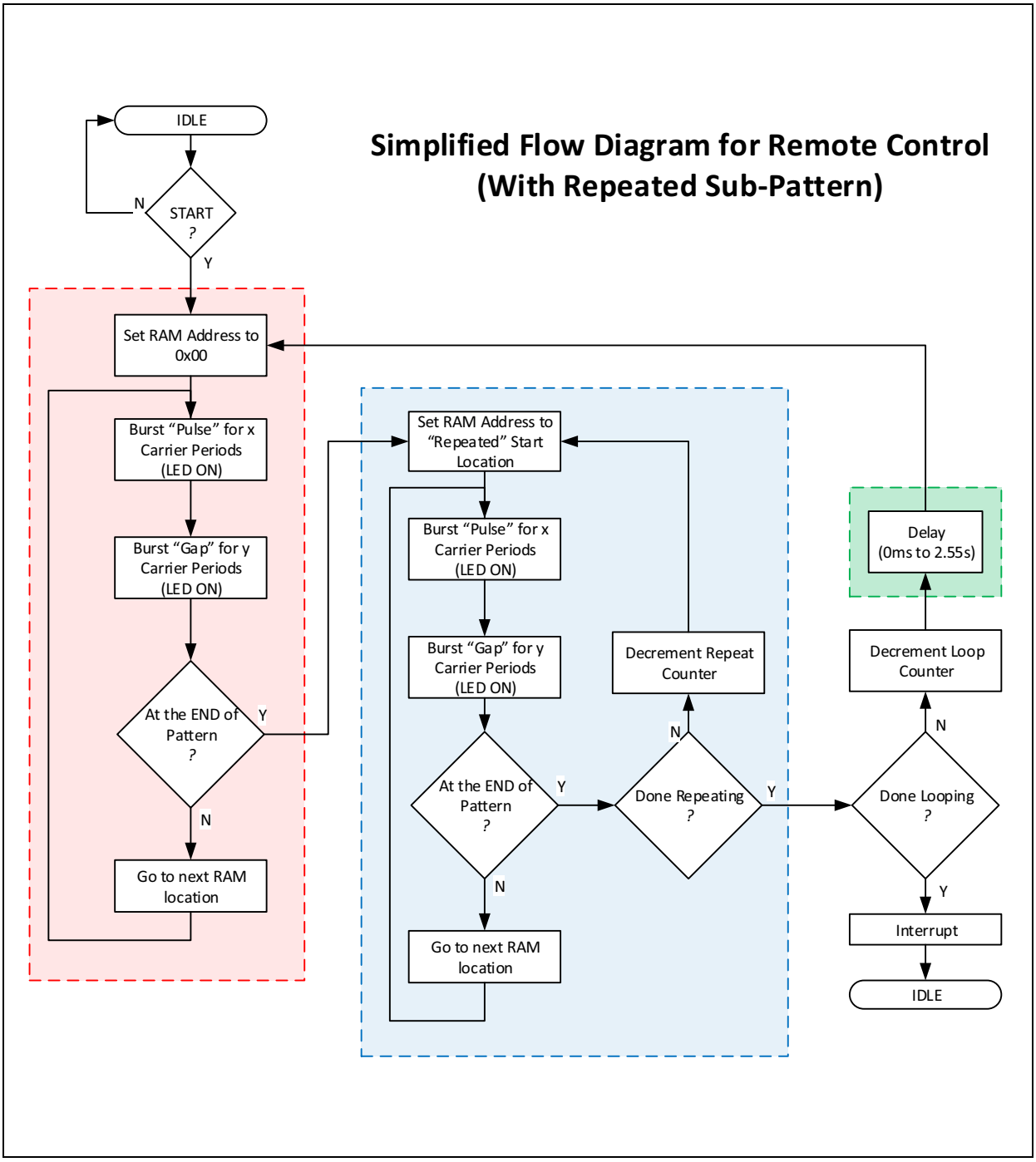
Protocols with "Repeated" Sub-Patterns: The blue box represents a repeated part of a pattern. These sub-patterns begin at an address within the red box and burst until the end of the pattern is encountered. The repeated sub-pattern can be reiterated 1 to 254 times, or continuously.

Digital Logic

The Simplified Flow Diagram depicts the basic premise of how an entire waveform is generated. Protocols of the form described in Figure 75 and Figure 76 can be generated using the mechanism depicted below. Any functionality show in the red, blue, or green boxes can be activated or omitted via control register settings or special operators in pattern RAM to produce virtually any waveform.

Typically, patterns are built by assembling pulses and gaps in a particular order. To this end the length of time for each pulse and gap, measured in multiples of carrier periods, as well as the order of each pulse/gap pair are specified in the equipment/button data. The remote control engine can directly accept the data in this format. Pulse/Gap order is stored in pattern RAM and pulse/gap time durations are stored in the Timewords table.

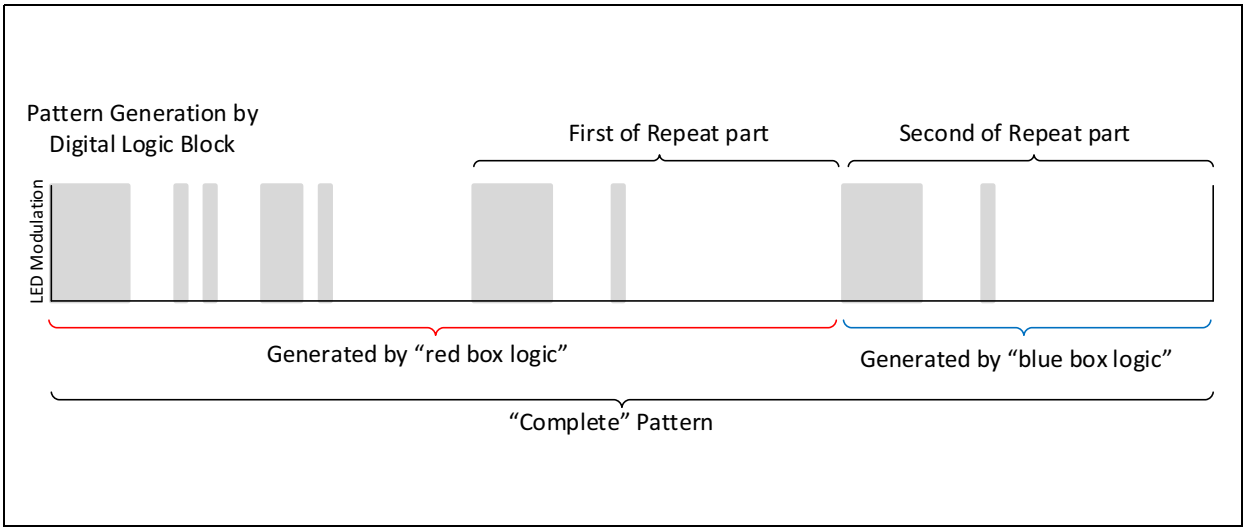
Figure 77:
Simplified Flow Diagram



Simplified Flow Diagram: The digital logic in the remote control engine has been tailored to fit the data format and protocol specifications for IR remote control. "Press and Release" type buttons (E.g. Power) are generated using the logic in the red box (logic in the blue box is not needed). "Press and Hold" type buttons (E.g. Volume+) are generated using logic in both the red and blue boxes.

The digital logic in the remote control engine has been tailored to fit the data format and protocol specifications for IR remote control. “Press and Release” type buttons (E.g. Power) are generated using the logic in the red box. “Press and Hold” type buttons (E.g. Volume+) are generated using logic in both the red and blue boxes. Figure 78 depicts how a command pattern with a repeated sub-pattern is created using the logic shown in the Simplified Flow Diagram. All of the “run-once” sub-pattern and the “first” instance of the “repeated” sub-pattern is actually run by the logic in the red box. The second instance of the “repeated” sub-pattern is run by the logic in the blue box.

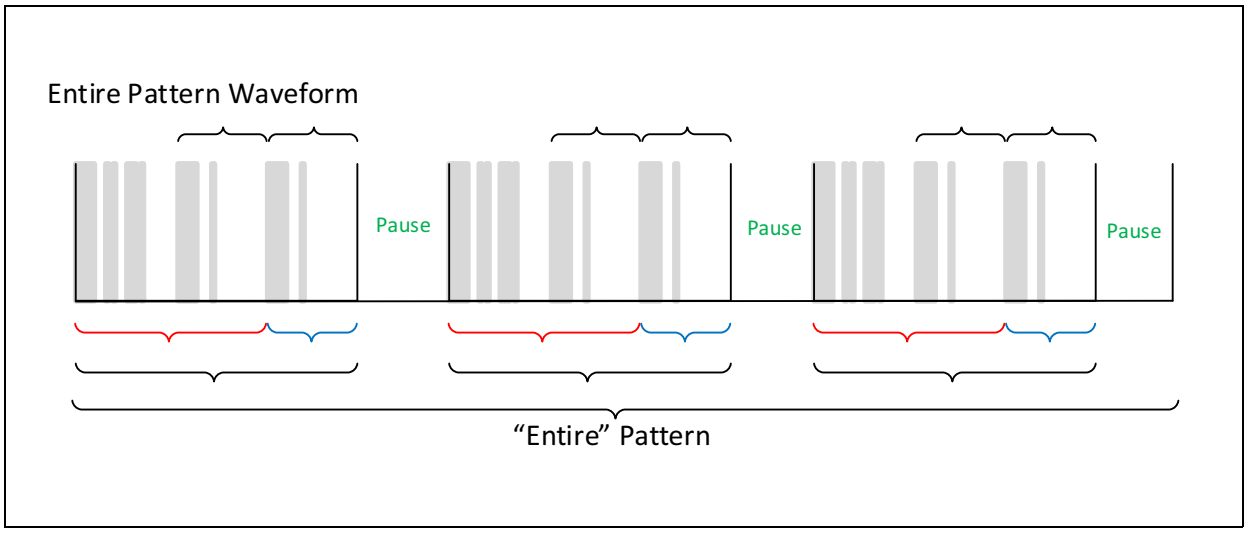
Figure 78:
Pattern Generation by Logical Block



Pattern Generation: All of the “one-time” sub-pattern and the “first” instance of the “repeated” sub-pattern is actually run by the logic in the red box. The second instance of the “repeated” sub-pattern is run by the logic in the blue box.

Complete patterns can also be automatically reburst from 1 to 254 times or continuously. Complete patterns can also be separated by a pause, or time delay, as generated by the logic in the green block. The entire pattern consists of a multiple of complete patterns and pause delays. During this length of time the entire pattern is bursting the IBUSY bit is set. Upon completion the IBUSY bit is cleared and the interrupts are set.

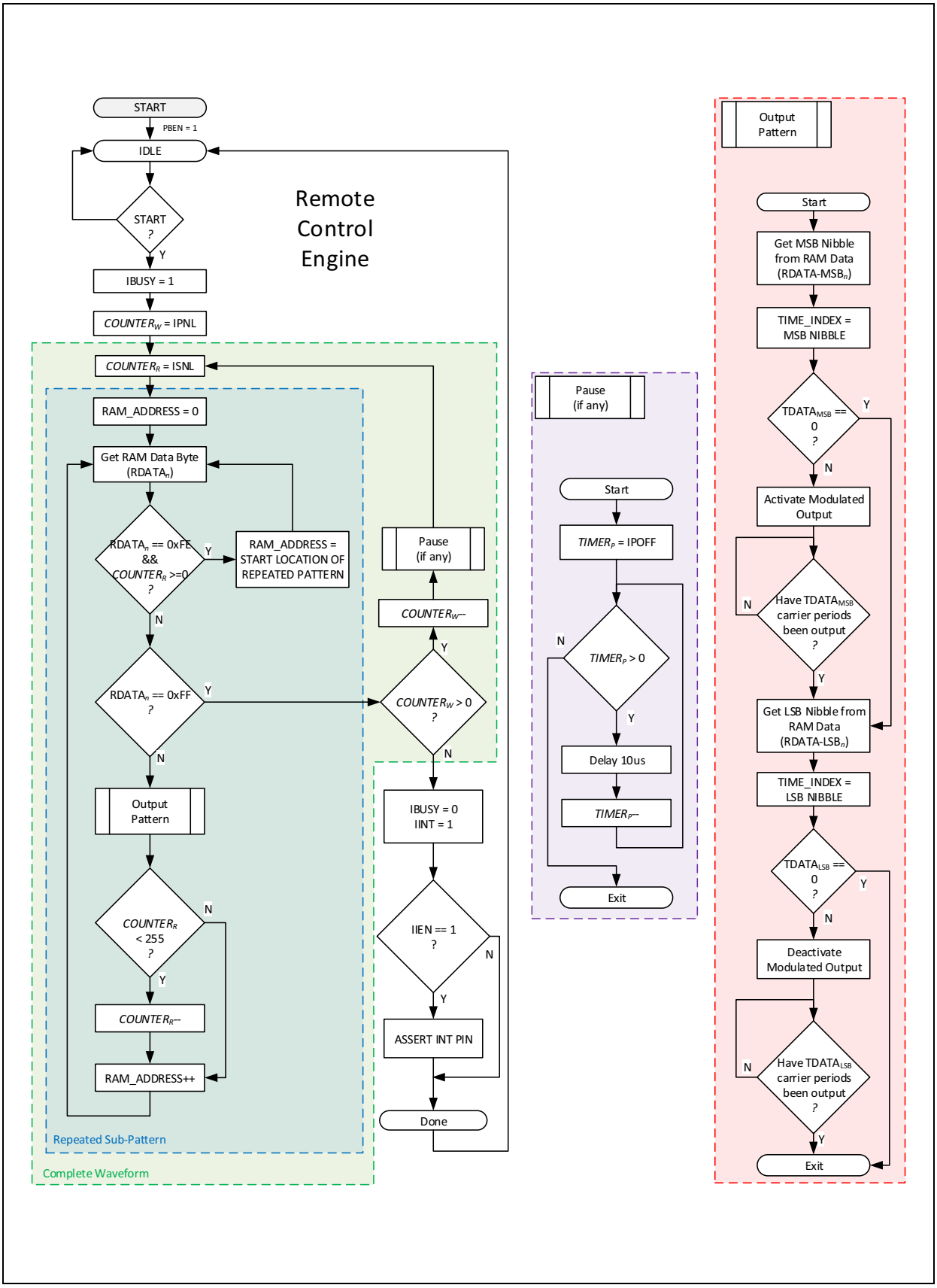
Figure 79:
Entire Pattern Waveform



Entire Pattern: Complete patterns can also be separated by a pause, or time delay, as generated by the logic in the green block. The entire pattern consists of a multiple of complete patterns and pause delays. During the length of time the entire pattern is bursting, the PBUSY bit is set.

Refer to the Remote Control Engine diagram which depicts the how the engine functions in great detail.

Figure 80:
Detailed Flow Diagram of the Remote Control Engine



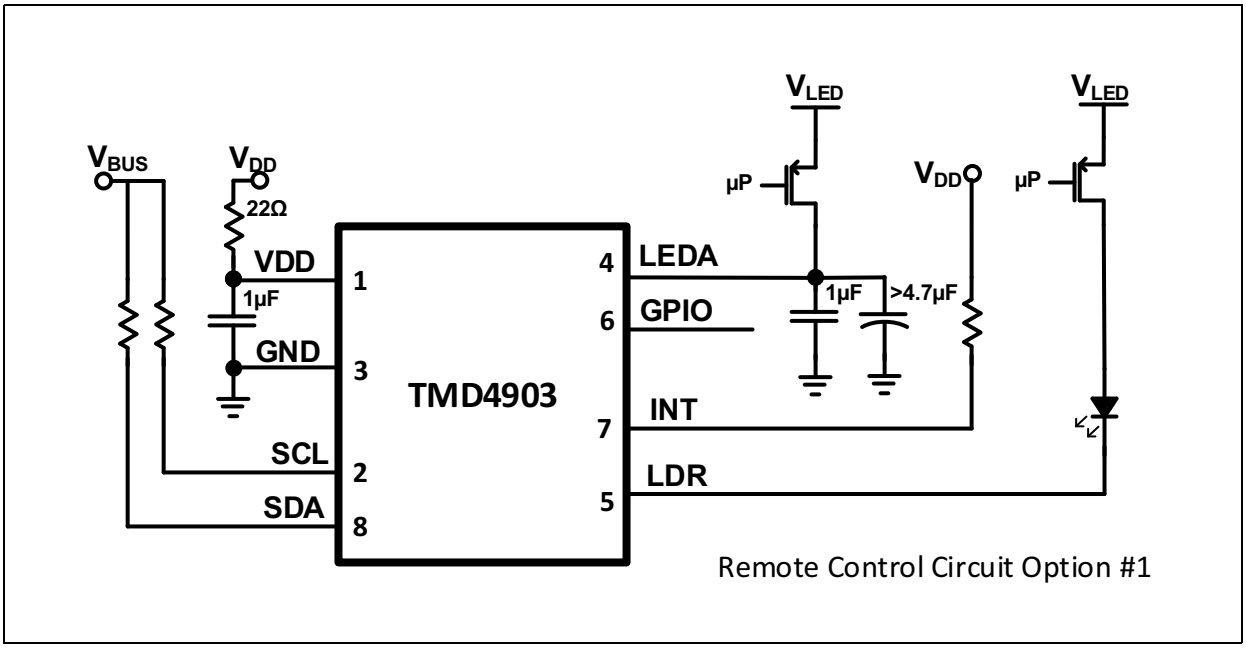
Remote Control Engine: Complete guide to the inner workings and use of the remote control functionality.

Electrical and Optical Output

The electrical or optical output of the remote control engine can be realized in three ways: use of the integrated top-facing LED, use of the LDR pin to directly drive an external LED, or use of the GPIO pin to drive an external FET and IR LED.

The LDR pin has a regulated current sink with selectable drive value. This is an attractive way to use an external LED without having an additional LED drive FET. If this method is to be used, then LEDA must be disconnected from the circuit. Since the cathode of the integrated LED is connected to the LDR pin internal to the module any current that is sourced through LEDA will reduce the current available on the external remote control LED. When the remote control functionality is not used the external LED must be electrically disconnected from the LDR pin to prevent it from illuminating.

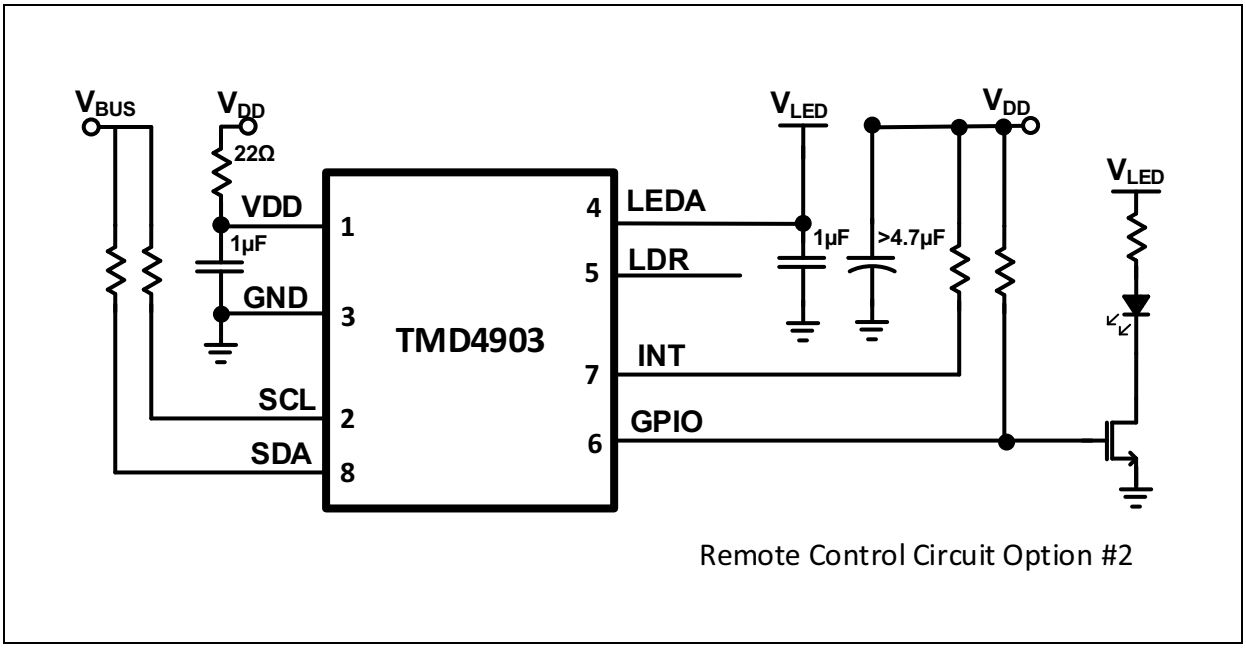
Figure 81:
External IR LED Using the LDR Pin



Recommended Connection: Option number one.

If the LDR pin is not used as the pattern output, the GPIO pin can be used. With this method both the LEDA and external remote control IR LED may remain connected to the LED power supply, but an additional FET is needed to drive the remote control LED.

Figure 82:
External IR LED Using the GPIO Pin



Recommended Connection: Option number two.

Example Waveform and Device Setup

A practical example is included to describe how each register is used and how to setup the device to burst a real waveform. The physical waveform, as seen on an oscilloscope, is described by the depiction in Figure 80. The Figure 83 depicts the mechanics to precondition the remote control engine for proper operation.

Figure 83:
Practical Example

Example

1. Carrier Frequency: 38kHz (T_{CAR} = 26us)

2. Duty Cycle = 25%

3. Non-repeat count=5 (LED_{ON}-LED_{OFF})
334-177, 22-22, 22-60, 60-22, 22-1541

4. Repeat count=2 (LED_{ON}-LED_{OFF})
334-88 22-3694
Run 2 times

5. Repeat compete pattern 3 times.

6. Delay 100us between complete patterns.

Time Words Table			
T_INDEX	T_DATA	I^2C Address, Data	
0	334	0x01, 0x01	0x00, 0x4E
1	177	0x03, 0x00	0x02, 0xB1
2	22	0x05, 0x00	0x04, 0x16
3	60	0x07, 0x00	0x06, 0x3C
4	1541	0x09, 0x06	0x08, 0x05
5	88	0x0B, 0x00	0x0A, 0x58
6	3694	0x0D, 0x0E	0x0C, 0x6E

Pattern Table	
ADDRESS	T_DATA
0	0x01
1	0x22
2	0x23
3	0x32
4	0x24
5	0x05
6	0x26
7	0xFE
8	0x05
9	0xFF

MSB points to index 0. Index 0 data is 334. LED will be on for 334 X T_{CAR}

LSB points to index 2. Index 2 data is 22. LED will be off for 22 X T_{CAR}

Byte following "0xFE" becomes the starting address of the repeated pattern.

STOP

IDLE
START
LED ON for 344 T_{CAR} / LED OFF for 177 T_{CAR}
LED ON for 22 T_{CAR} / LED OFF for 22 T_{CAR}
LED ON for 22 T_{CAR} / LED OFF for 60 T_{CAR}
LED ON for 60 T_{CAR} / LED OFF for 22 T_{CAR}
LED ON for 22 T_{CAR} / LED OFF for 1541 T_{CAR}
LED ON for 334 T_{CAR} / LED OFF for 88 T_{CAR}
LED_{ON} for 572us / LED_{OFF} for 96ms → LED ON for 22 T_{CAR} / LED OFF for 3694 T_{CAR}
To run two times, must repeat once. → LED ON for 334 T_{CAR} / LED OFF for 88 T_{CAR} ; LED ON for 22 T_{CAR} / LED OFF for 3694 T_{CAR}
Delay 100us
To run complete pattern three times, must repeat twice. → Pattern / Delay 100us ; Pattern / Delay 100us
IDLE

Carrier Frequency:
IBT = 0x68 (26us/250ns)

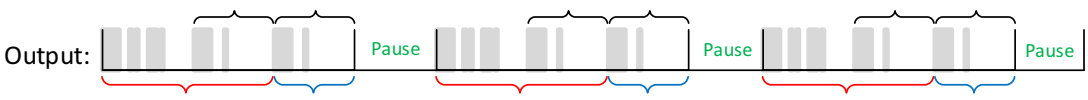
Duty Cycle:
ICONFIG2 = 0x02

"Repeated sub-pattern" Repeat count=2:
ISNL = 0x01

"Complete sub-pattern" Repeat count=3:
IPNL = 0x02

Delay 100us between complete patterns:
IPOFF = 0x0A (100us/10us)

START:
Write a 0x02 to ISTART.



Practical Example: Device registers and RAM are loaded with values to generate a real remote control waveform.

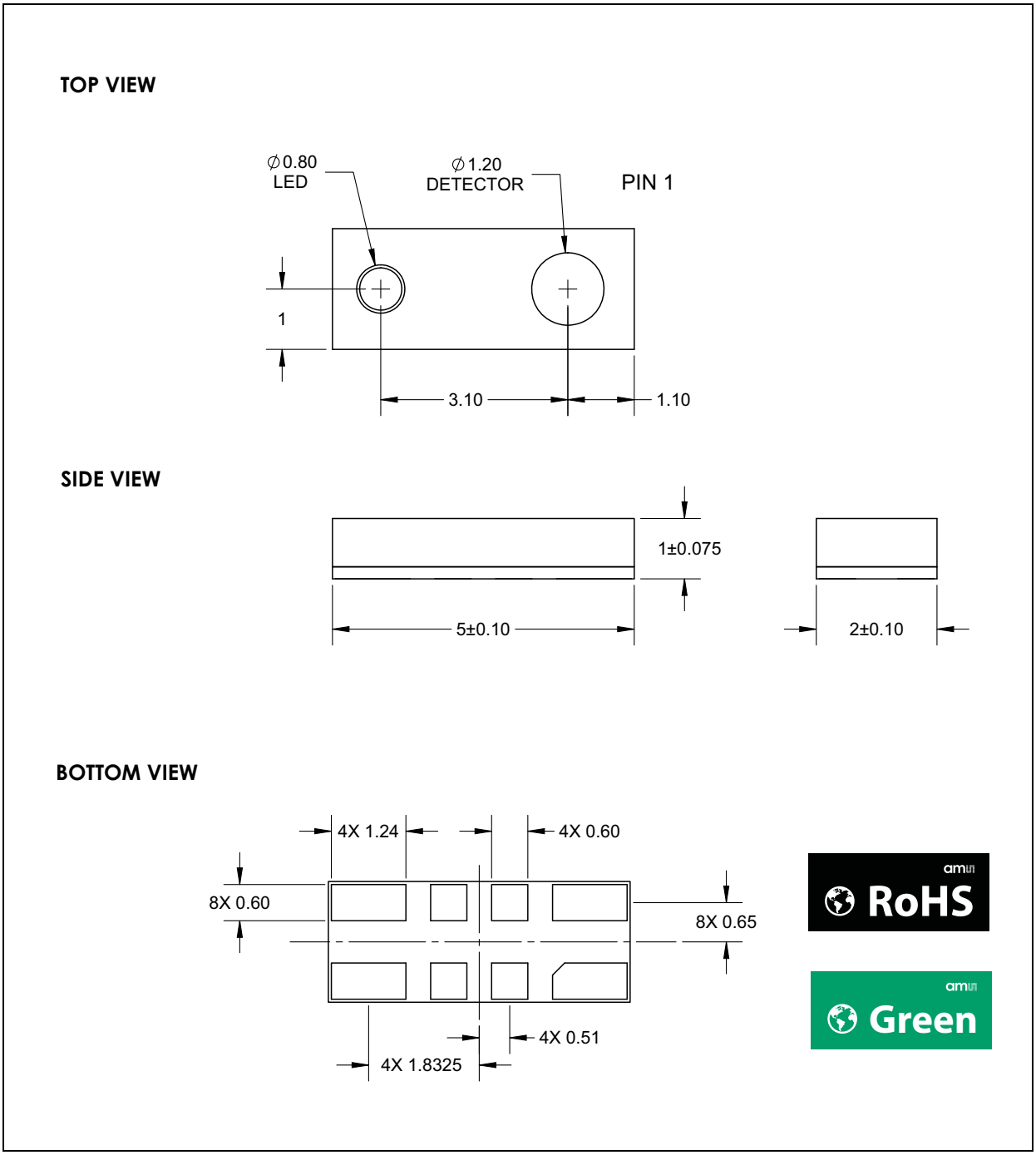
Protocol Accommodation Checklist

The Remote Control pattern generation/transmission feature can be configured to broadcast virtually all IR communication protocols used for commanding consumer electronic devices. There are many different remote control protocols currently in use; and to meet the multitude of requirements the remote control engine has been designed to be flexible. In general, a protocol functions within the following transmission specifications can be accommodated:

- Carrier periods are selectable in 250ns increments. Carrier frequencies are in the range of 15.625 kHz to 460 kHz. Protocols that do not use carriers can also be accommodated.
- Duty cycle of the carrier is selectable: 50%, 37%, 25%, and 12%. Exact LED duty cycle depends on the external circuit.
- Pulse (LED on) and Gap (LED off) widths are a multiple of carrier periods (T_{CAR}). Pulse and Gap length is selectable from 0 to 65535 carrier periods. Patterns with exceptionally long pulses or gaps (I.e. longer than 65535 carrier periods) may be accommodated. This requires setting contiguous pattern ram locations, but results in a glitch-free long pulse/gap.
- A dedicated “time word” RAM table contains sixteen, 16-bit words which are used to set pulse and gap widths. Simply stated, a pattern must contain sixteen or fewer unique pulse/gap widths. Note: patterns containing more than 16 unique pulse/gap widths may be accommodated by using the 16-bit timewords as “building blocks” to form longer pulse/gaps. For example, if a pattern has a pulse/gap of both $3T_{CAR}$ and $6T_{CAR}$, then only the $3T_{CAR}$ need be represented in the Time Word table; then the $6T_{CAR}$ can be generated by indexing into the $3T_{CAR}$ twice (This requires the use of additional pattern RAM).
- A dedicated “pattern” RAM contains 256 bytes of data. Each byte indexes into the Timeword table to form a complete pulse and gap pair. A pattern that does not contain a “repeated” sub-pattern must have 255 or fewer pulse/gap pairs. A pattern that contains a “repeated” sub-pattern must have 254 or fewer pulse/gap pairs, not including the *additional* repetitions of the “repeated” sub-pattern.
- Entire patterns can be reburst up to an additional 255 times and are separated by a selectable delay of 0us to 2.55s, in 10us increments.

Package Drawings & Markings

Figure 84:
TMD4903 Module Dimensions



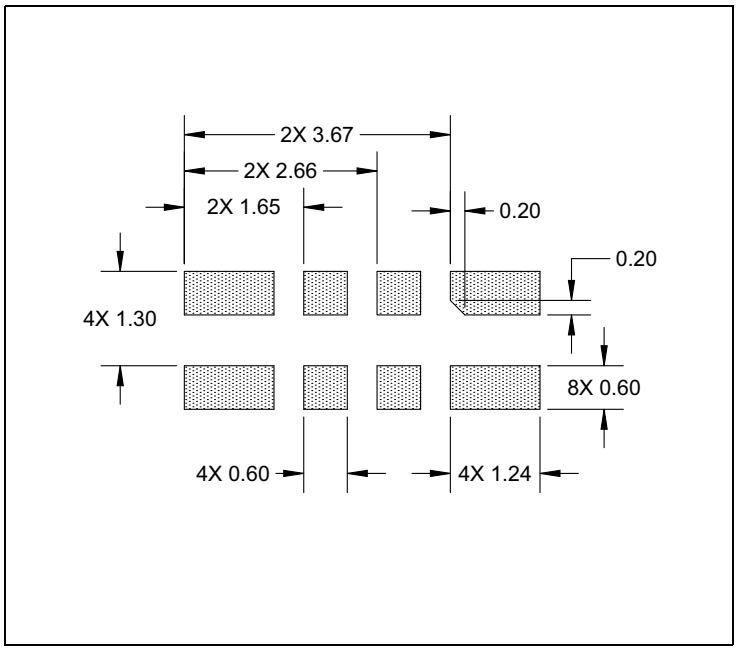
Note(s) and/or Footnote(s):

1. All linear dimensions are in millimeters.
2. Dimension tolerances are ±0.05mm unless otherwise noted.
3. Contacts are copper with NiPdAu plating.
4. This package contains no lead (Pb).
5. This drawing is subject to change without notice.
6. Measurement guarantee by lot acceptance testing using 20 units.

PCB Pad Layout

Suggested PCB pad layout guidelines for the surface mount module are shown. Flash Gold is recommended as a surface finish for the landing pads.

Figure 85:
Recommended PCB Pad Layout

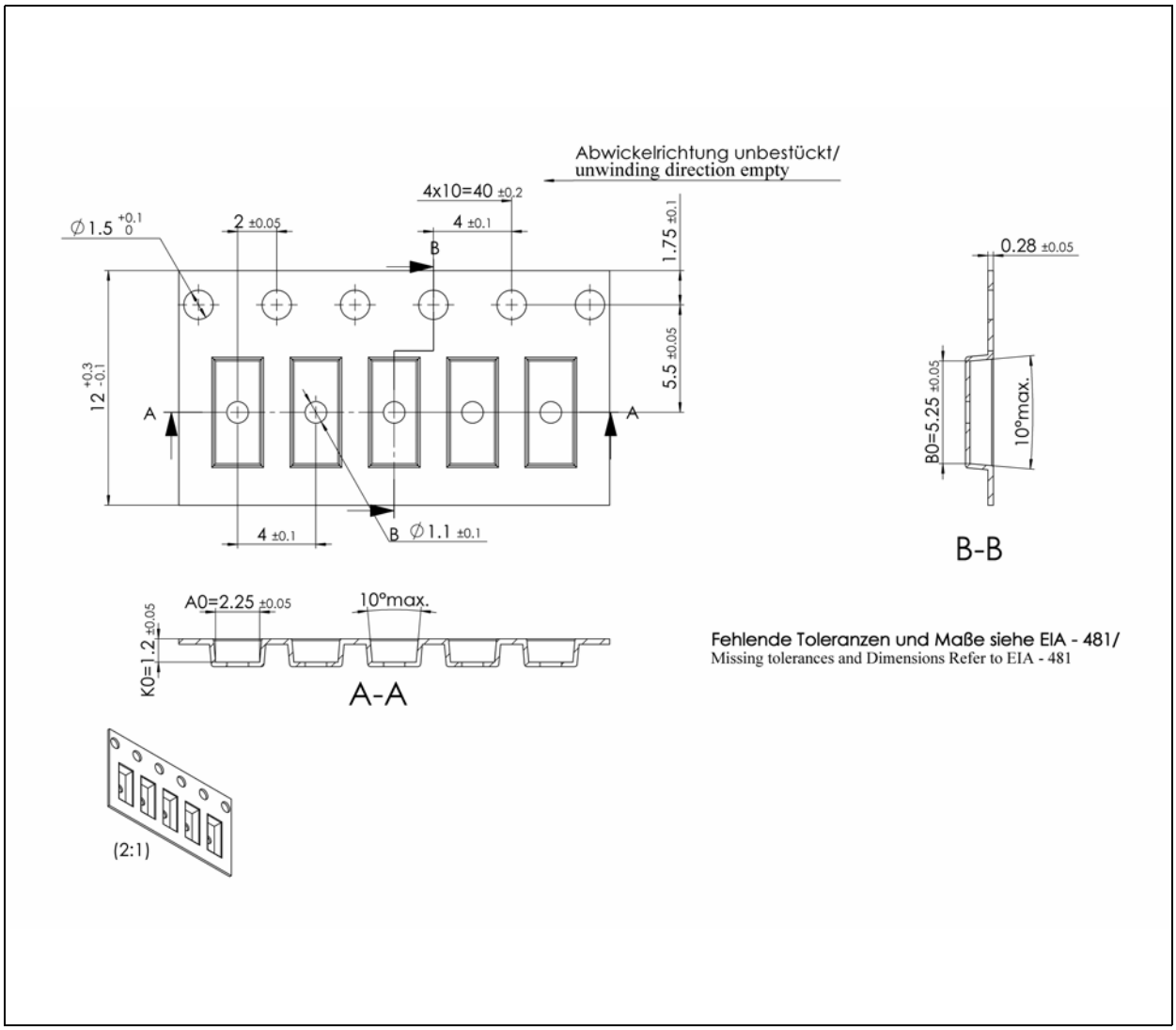


Note(s) and/or Footnote(s):

1. All linear dimensions are in millimeters.
2. Dimension tolerances are ±0.05mm unless otherwise noted.
3. This drawing is subject to change without notice.

Mechanical Data

Figure 86:
Tape and Reel Mechanical Drawing



Note(s) and/or Footnote(s):

1. All linear dimensions are in millimeters. Dimension tolerance is ± 0.10 mm unless otherwise noted.
2. The dimensions on this drawing are for illustrative purposes only. Dimensions of an actual carrier may vary slightly.
3. Symbols on drawing Ao, Bo, and Ko are defined in ANSI EIA Standard 481−B 2001.
4. Each reel is 330 millimeters in diameter and contains 5000 parts.
5. **ams** packaging tape and reel conform to the requirements of EIA Standard 481−B.
6. In accordance with EIA standard, device pin 1 is located next to the sprocket holes in the tape.
7. This drawing is subject to change without notice.

Soldering & Storage Information

Soldering Information

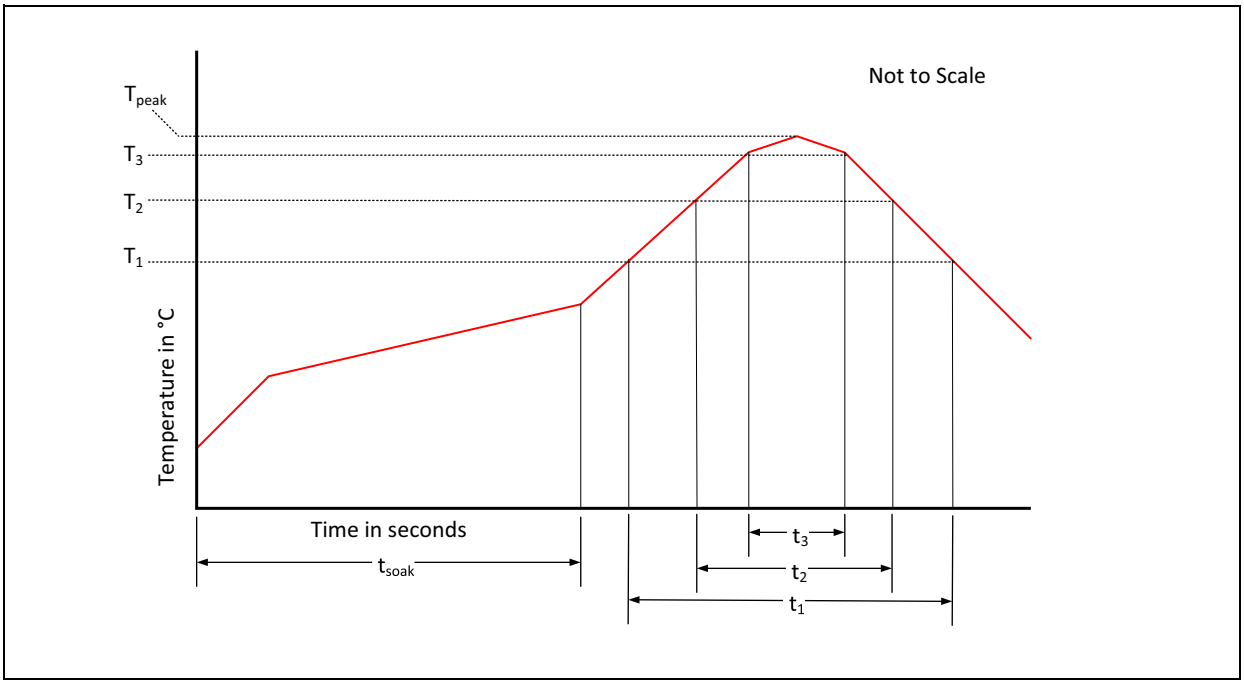
The module has been tested and has demonstrated an ability to be reflow soldered to a PCB substrate.

The solder reflow profile describes the expected maximum heat exposure of components during the solder reflow process of product on a PCB. Temperature is measured on top of component. The components should be limited to a maximum of three passes through this solder reflow profile.

Figure 87:
Solder Reflow Profile

Parameter	Reference	Device
Average temperature gradient in preheating		2.5 °C/sec
Soak time	t_{soak}	2 to 3 minutes
Time above 217 °C (T1)	t_1	Max 60 sec
Time above 230 °C (T2)	t_2	Max 50 sec
Time above T_{peak} – 10 °C (T3)	t_3	Max 10 sec
Peak temperature in reflow	T_{peak}	260 °C
Temperature gradient in cooling		Max -5 °C/sec

Figure 88:
Solder Reflow Profile Graph



Storage Information

Moisture Sensitivity

Optical characteristics of the device can be adversely affected during the soldering process by the release and vaporization of moisture that has been previously absorbed into the package. To ensure the package contains the smallest amount of absorbed moisture possible, each device is baked prior to being dry packed for shipping.

Devices are dry packed in a sealed aluminized envelope called a moisture-barrier bag with silica gel to protect them from ambient moisture during shipping, handling, and storage before use.

Shelf Life

The calculated shelf life of the device in an unopened moisture barrier bag is 12 months from the date code on the bag when stored under the following conditions:

- Shelf Life: 12 months
- Ambient Temperature: <40°C
- Relative Humidity: <90%

Rebaking of the devices will be required if the devices exceed the 12 month shelf life or the Humidity Indicator Card shows that the devices were exposed to conditions beyond the allowable moisture region.

Floor Life

The module has been assigned a moisture sensitivity level of MSL 3. As a result, the floor life of devices removed from the moisture barrier bag is 168 hours from the time the bag was opened, provided that the devices are stored under the following conditions:

- Floor Life: 168 hours
- Ambient Temperature: <30°C
- Relative Humidity: <60%

If the floor life or the temperature/humidity conditions have been exceeded, the devices must be rebaked prior to solder reflow or dry packing.

Rebaking Instructions

When the shelf life or floor life limits have been exceeded, rebake at 50°C for 12 hours.

Ordering & Contact Information

Figure 89:
Ordering Information

Ordering Code	Address	Interface	Delivery Form
TMD49033	0x39	I^2C bus = 1.8V Interface	Tape & Reel
TMD49037 (1)	0x29	I^2C bus = 1.8V Interface	Tape & Reel

Note(s) and/or Footnote(s):

1. Contact **ams** for availability.

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Product Preview	Pre-Development	Information in this datasheet is based on product ideas in the planning phase of development. All specifications are design goals without any warranty and are subject to change without notice
Preliminary Datasheet	Pre-Production	Information in this datasheet is based on products in the design, validation or qualification phase of development. The performance and parameters shown in this document are preliminary without any warranty and are subject to change without notice
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Revision Information

Changes from 1-11 (2015-Apr-23) to current revision 1-12 (2015-May-14)	Page
Updated Section title	
Updated text under General Description	1
Updated Figure 1	2
Updated Applications	2
Updated Figure 2	3
Updated Figure 4	4
Updated Figure 5	5
Updated Figure 10	9
Updated title of Figure 20	14
Updated text under I^2C Protocol section	16
Updated Figure 23	17
Updated Figure 24 and added a note under it	18
Updated text under Detailed Description	19
Updated Figure 25	20
Updated Figure 26	23
Updated text under ALS Interrupt Threshold Registers	27
Updated text under Proximity Interrupt Threshold Registers	27
Updated Figure 32	28
Updated FIgure 33	29
Updated Proximity Configuration Register Zero section	30
Updated text under Proximity Configuration Register One	31
Updated Figure 37	32
Updated Figure 38	33
Updated Figure 39	33
Updated text under CRGB Data Registers	34
Updated text under Proximity Data Registers	35

Changes from 1-11 (2015-Apr-23) to current revision 1-12 (2015-May-14)	Page
Updated Figure 47	40
Updated Figure 49	41
Updated Figure 54	44
Updated text under Proximity Offset Registers	48
Added Autozero Configuration Register	49
Updated Figure 63	50
Added Calibration Configuration Register One	52
Updated Figure 67	55
Updated Figure 89	79

Note(s) and/or Footnote(s):

1. Page and figure numbers for the previous version may differ from page and figure numbers in the current revision.
2. Correction of typographical errors is not explicitly mentioned.

Content Guide